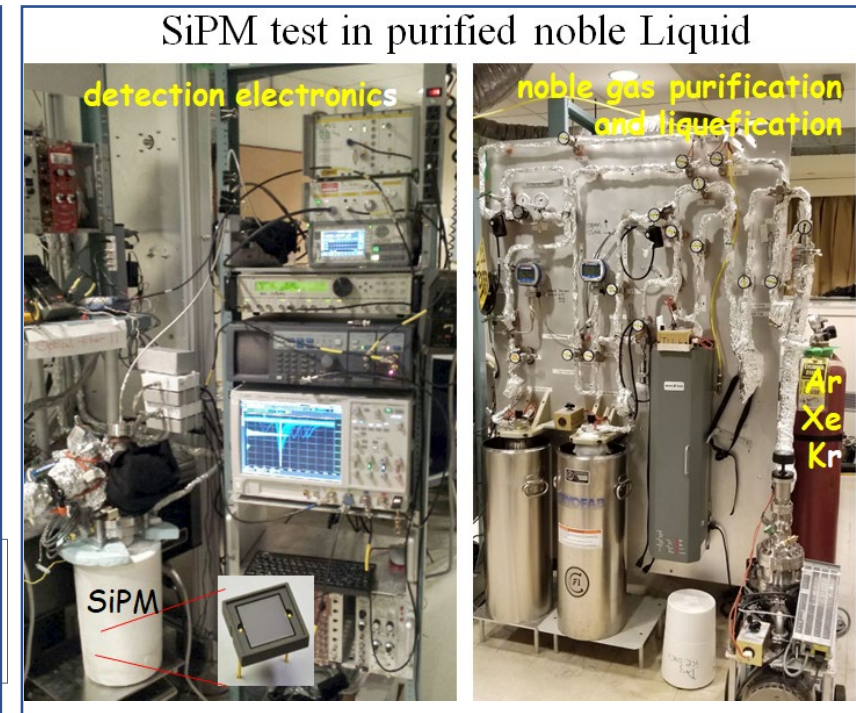
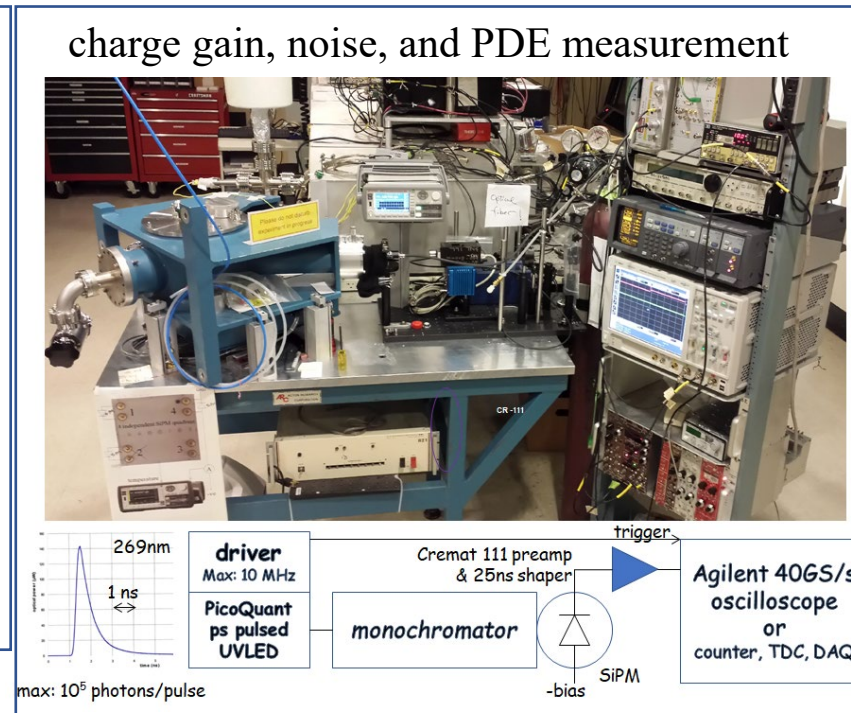
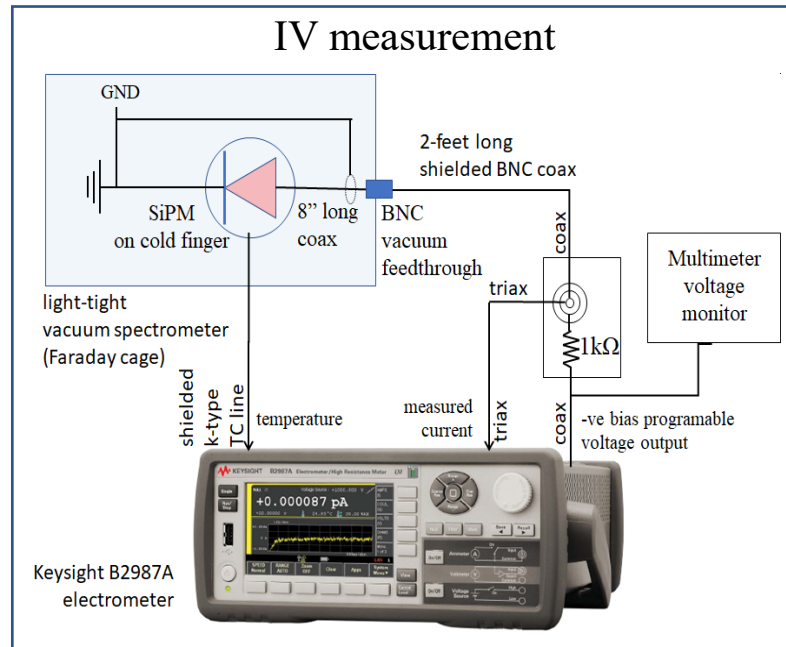
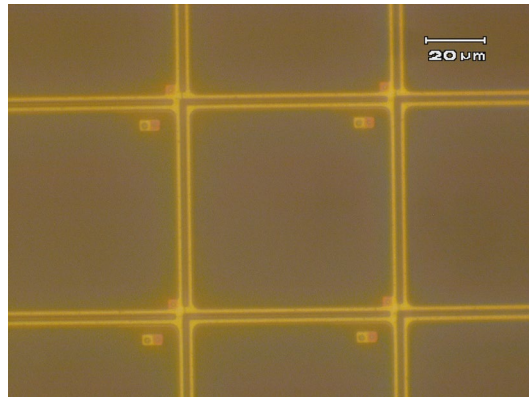
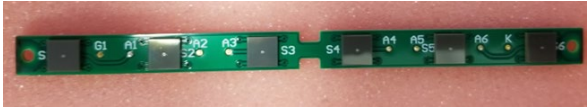


The Instrumentation Division at BNL has been testing SiPMs from various vendors in the past years; primary targeted to operate SiPMs in cryogenic temperature and in noble liquids.

- Packaging and bond bare SiPM chips to various carriers
- Current-voltage (IV) characterization: at room temperature, 165K, 85K in vacuum, LN₂, and in purified LAr, LXe, and LKr
- Charge gain, μ cell and terminal capacitance, quench resistance, $V_{\text{breakdown}}$, I_{dark}
- time correlated and time uncorrelated avalanche noise measurements: optical cross-talk (CT), after-pulse (AP), and thermally activated dark count (DCR), respectively.
- photodetection efficiency (PDE) from VUV to NIR wavelength range and photon number resolving (PNR) capability.

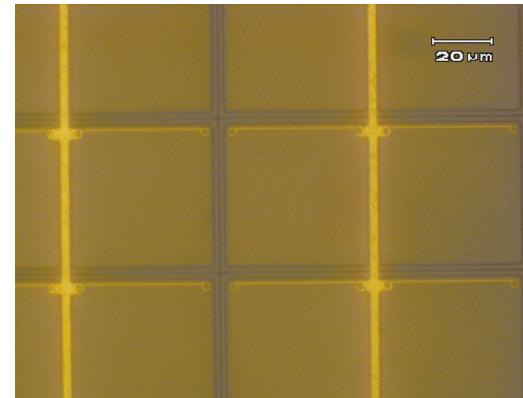
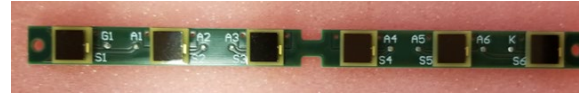


DUNE S13360-6075-HS-HRQ
 high R_q , normal V_{bd}



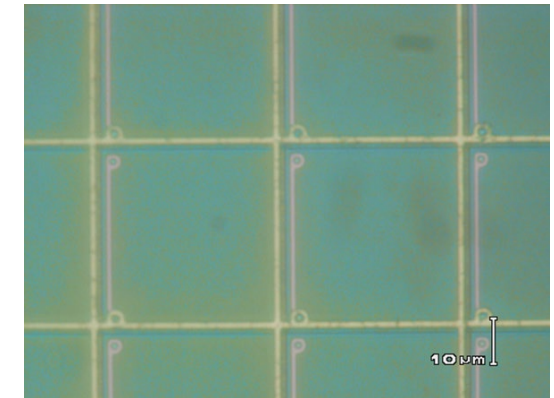
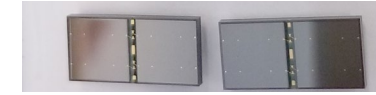
| S13360-6075-HS-HRQ | |
|--------------------|---------------------|
| area | 6x6 mm ² |
| pixel size | 75 μm |
| # of pixels | 6364 |
| V_{bd} (RT, LN2) | 51 V, 41 V |
| Capacitance | 1.9 nF |

DUNE FBK triple-trench 50μm
 low V_{bd}



| FBK triple-trench | |
|--------------------|---------------------|
| area | 6x6 mm ² |
| pixel size | 50 μm |
| # of pixels | 11188 |
| V_{bd} (RT, LN2) | 31 V, 27 V |
| Capacitance | 2.6 nF |

Broadcom AFBR-S4N66P024M
 40μm low V_{bd}

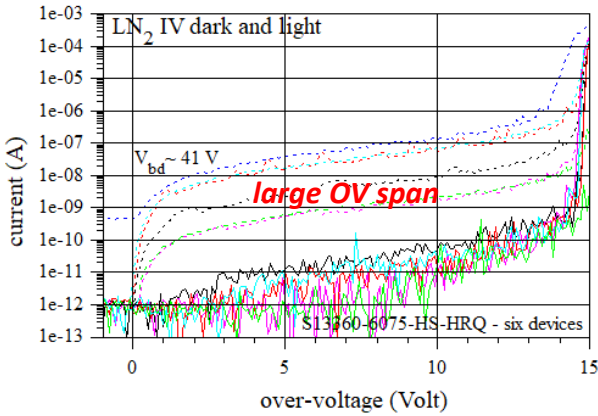
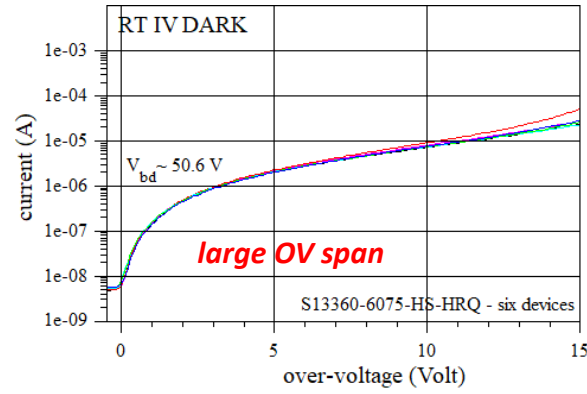


| Broadcom | |
|--------------------|---------------------|
| area | 6x6 mm ² |
| pixel size | 40 μm |
| # of pixels | 22428 |
| V_{bd} (RT, LN2) | 32.3 V, 27 V |
| Capacitance | 2.9 nF |

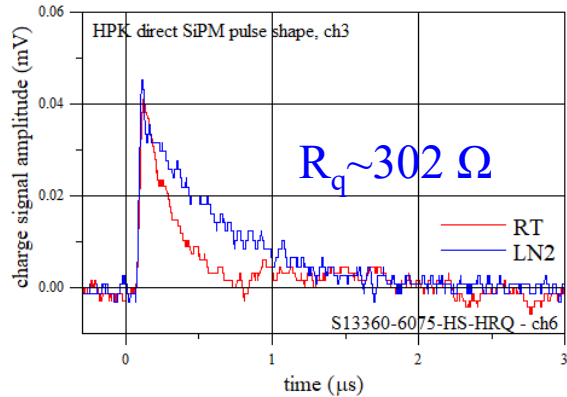
lower V -breakdown → higher capacitance → higher power to drive readout electronics

DUNE S13360-6075-HS-HRQ high R_q , normal V_{bd}

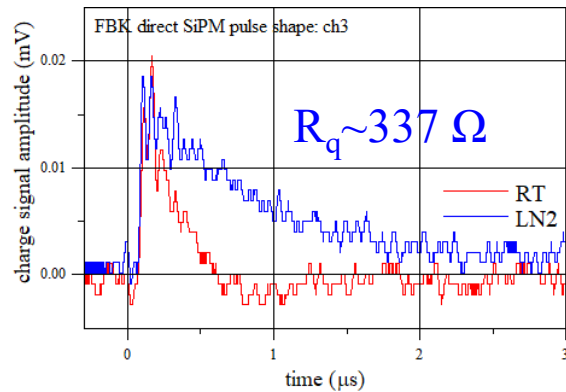
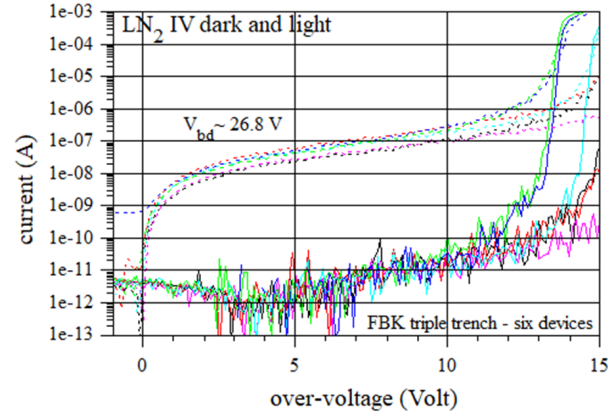
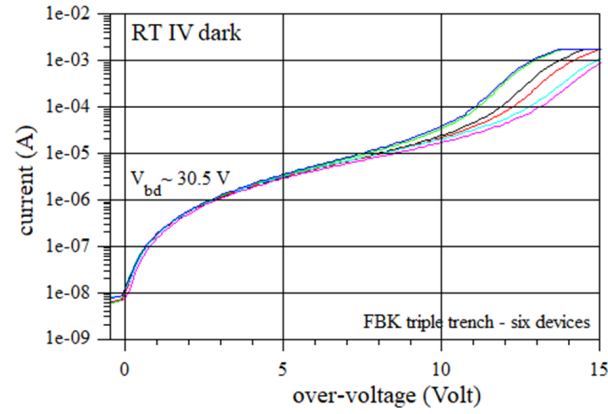
IV
Room Temp.



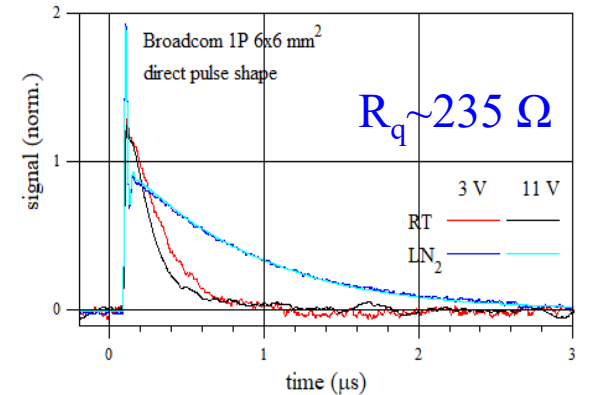
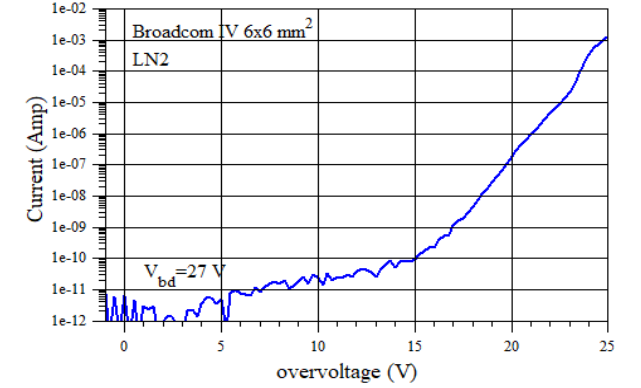
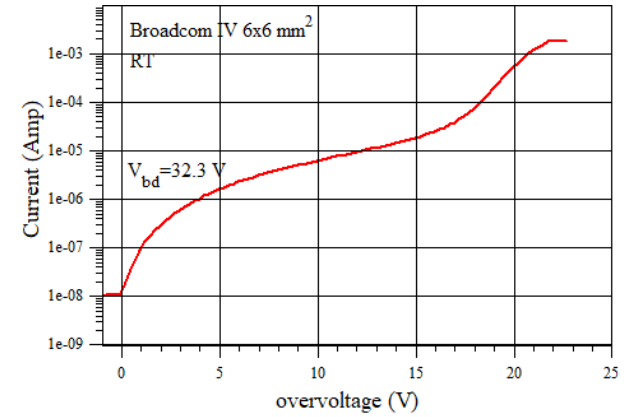
direct
pulse shape



DUNE FBK triple-trench 50μm low V_{bd}

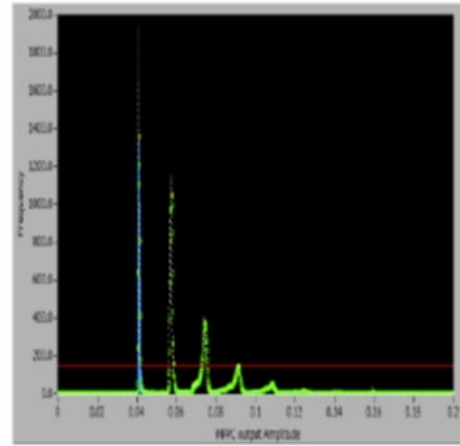
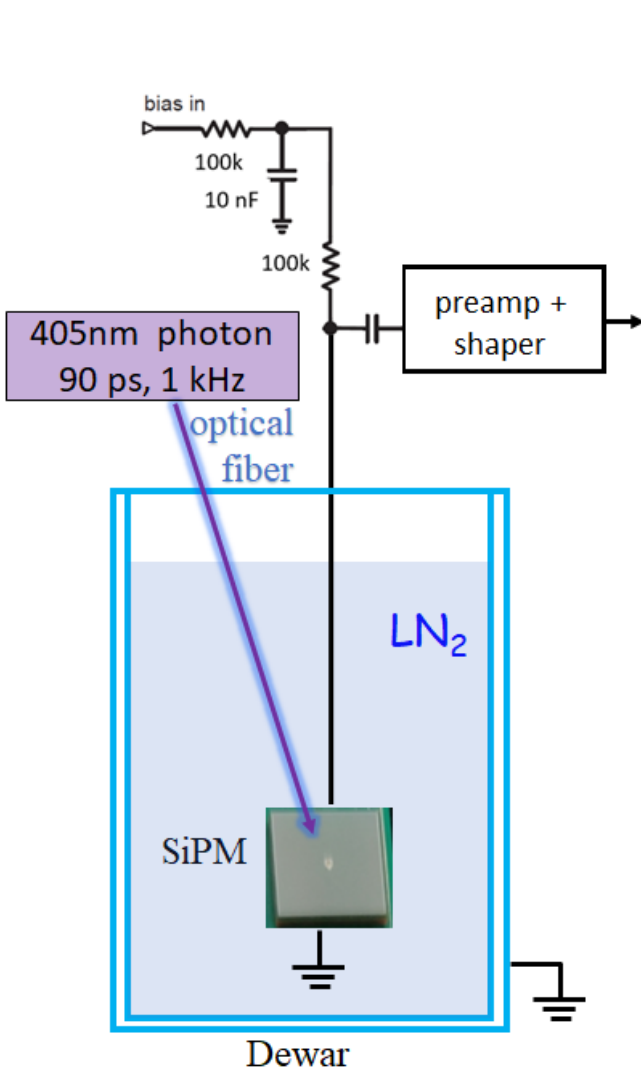


Broadcom



PDE, correlated noise, etc...

PDE is calculated by fitting a Poisson distribution to the photoelectron spectrum



$$P(n, x) = \frac{n^x e^{-n}}{x!}$$

$$P(n, 0) = \frac{\left(\frac{N_{ped}}{N_{tot}}\right)}{\left(\frac{N_{ped}^{dark}}{N_{tot}^{dark}}\right)} \quad (\leftarrow \text{dark pulse correction})$$

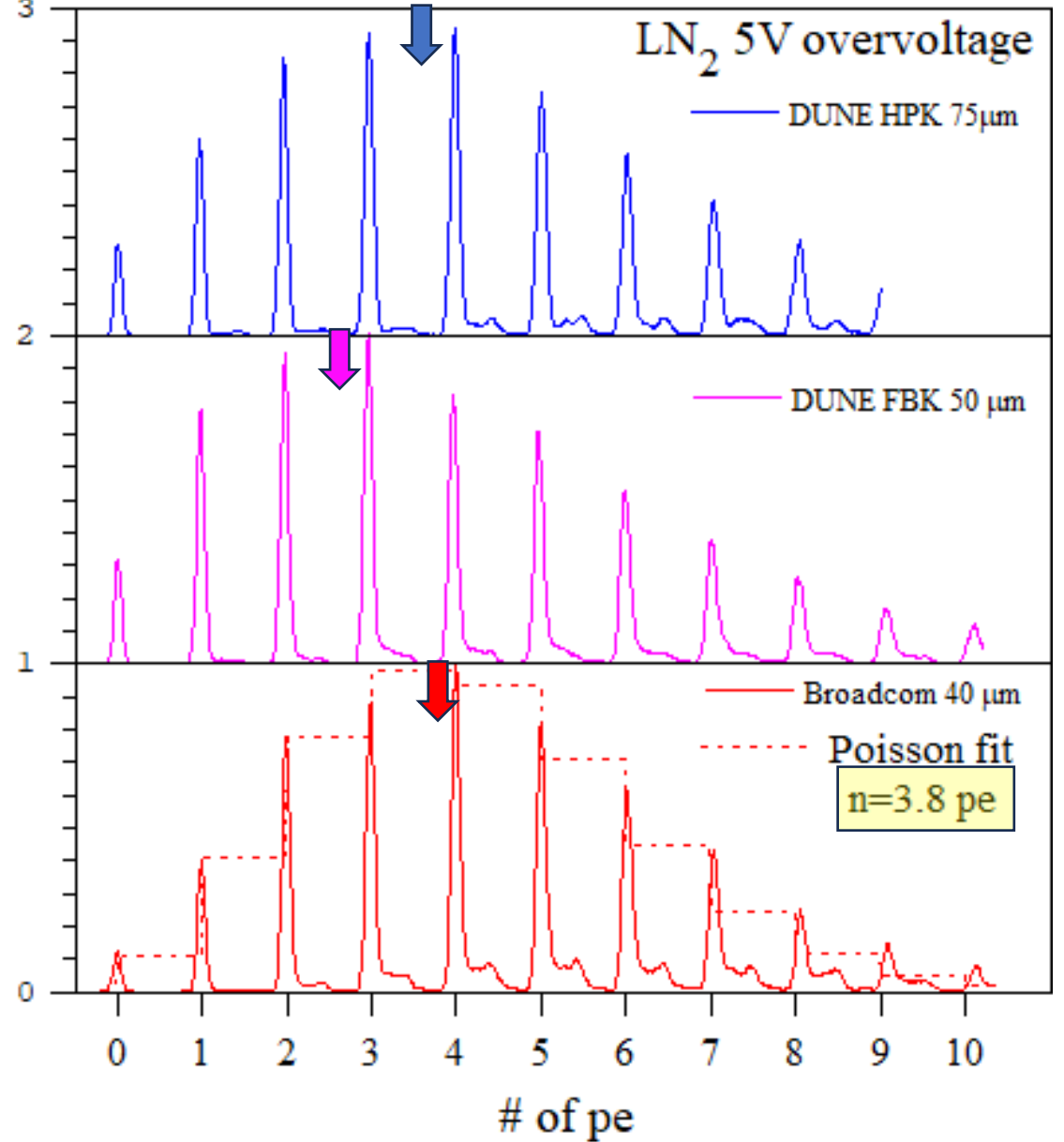
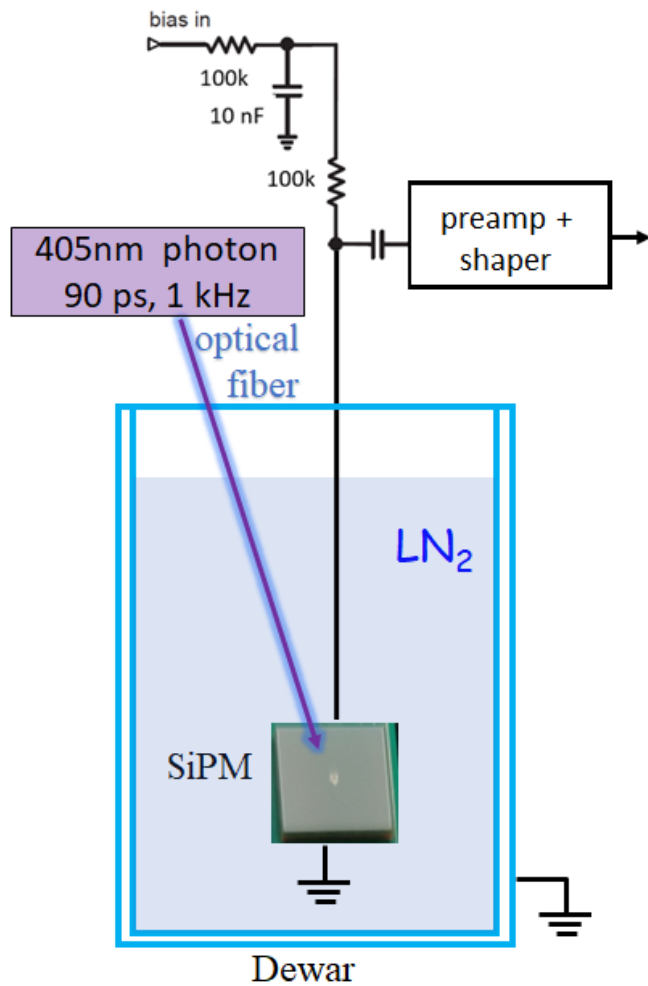
$$\rightarrow n = -\ln\left(\frac{\frac{N_{ped}}{N_{tot}}}{\frac{N_{ped}^{dark}}{N_{tot}^{dark}}}\right) = -\ln\left(\frac{N_{ped}}{N_{tot}}\right) + \ln\left(\frac{N_{ped}^{dark}}{N_{tot}^{dark}}\right)$$

n : average number of photons detected by MPPC
 x : number of photons detected by MPPC

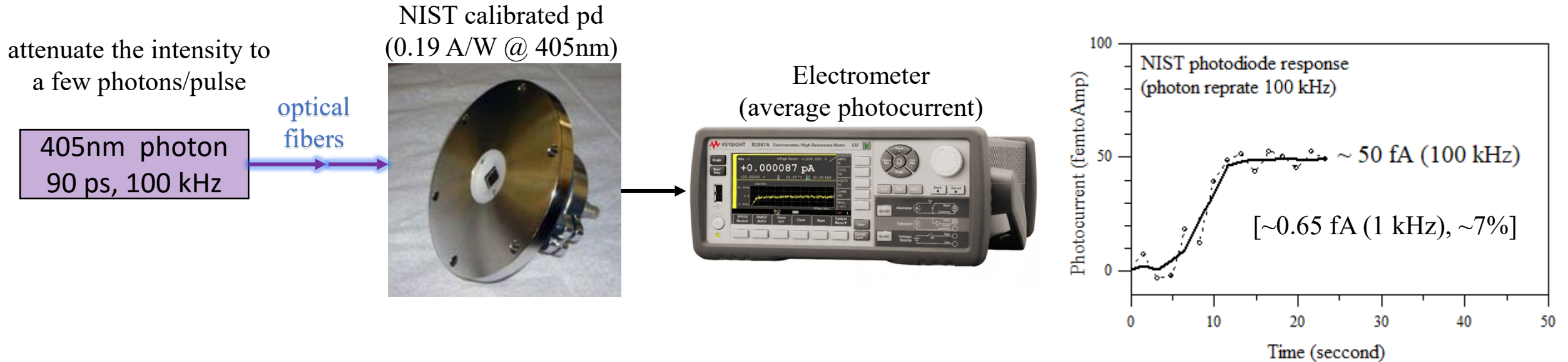
N_{ped} : number of events at 0 p.e. during pulsed light measurement
 N_{tot} : number of all events during pulsed light measurement
 N_{ped}^{dark} : number of events at 0 p.e. in dark state
 N_{tot}^{dark} : number of all events in dark state

n = Poisson fitted mean number of photoelectrons

relative PDE in LN₂ (Broadcom, DUNE FBK, DUNE HPK)



Number of incidence photons is determined from the measured photocurrent at the selected wavelength from a NIST calibrated photodiode



$$\# \text{ of } 405 \text{ nm photons} = \frac{0.65 \text{ fA}}{(1 \text{ kHz}) \left(0.19 \frac{\text{A}}{\text{W}}\right) (1.6 \times 10^{-19} \text{ J/eV}) (3.06 \text{ eV})} (0.86) = 6.01 \text{ photons/pulse}$$

PDE in LN₂ (Broadcom, DUNE FBK, DUNE HPK)

$$\text{PDE} = \frac{\# \text{ pe}}{\# \text{ hv}} = F_{\text{geometry}} \times \text{QE}_{e-p}(\lambda, T) \times \varepsilon_{\text{avalanche}}(\Delta V, \lambda, T)$$

↑
geometric
↑
photon
↑
photoelectron

$$\text{PDE (Broadcom, 405 nm, 5V, LN}_2) = \frac{\# \text{ photoelectrons out}}{\# \text{ photons in}} = \frac{3.8}{6.01} = 0.63$$

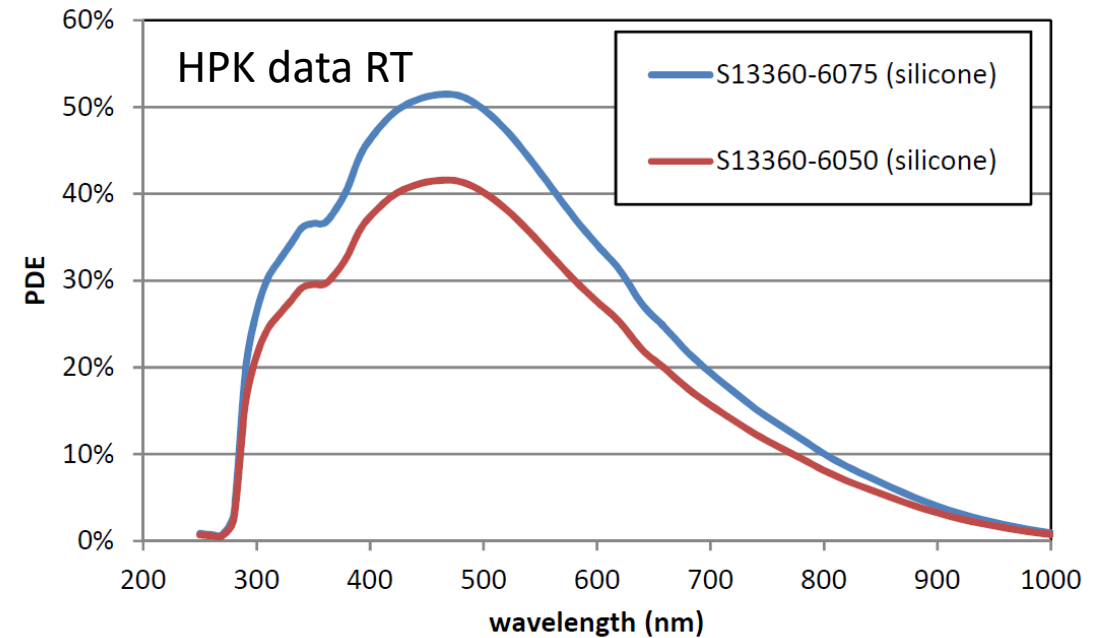
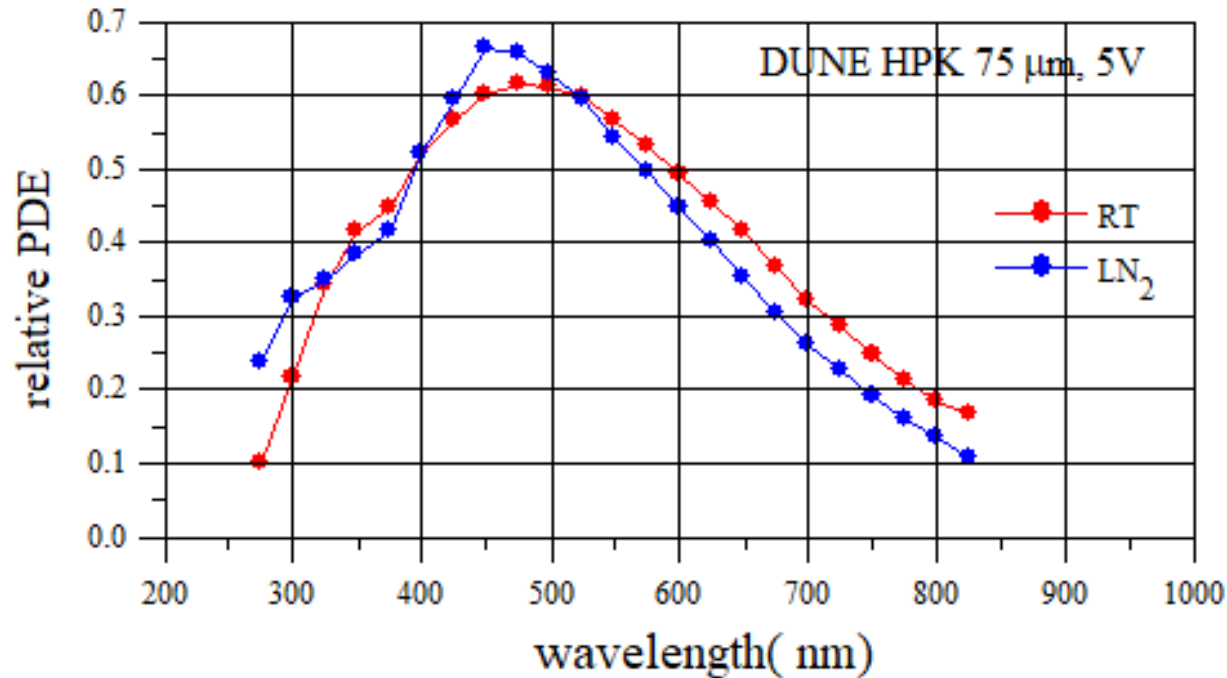
| PDE @ 405 nm 5V OV in LN2 | Poisson fitted n-pe | absolute PDE (±7%) | Spec. RT |
|------------------------------|------------------------|-----------------------|-------------|
| DUNE HPK 75 μm | 3.15 | 0.52 | ~0.47 |
| DUNE FBK 50 μm | 2.93 | 0.48 | n/c |
| Broadcom 40 μm | 3.8 | 0.63 | ~0.62 |

DUNE HPK: PDE spectral response – use white light source and calibrate against NIST photodiode

$$PDE_{\lambda} = [spectral\ reponse]_{\lambda} \times \frac{[PDE_{pulse}]_{405nm}}{[spectral\ reponse]_{405nm}}$$

noted: CT & AP – photoelectron effect, wavelength independent

PDE (QE) = photon effect, depends on wavelength



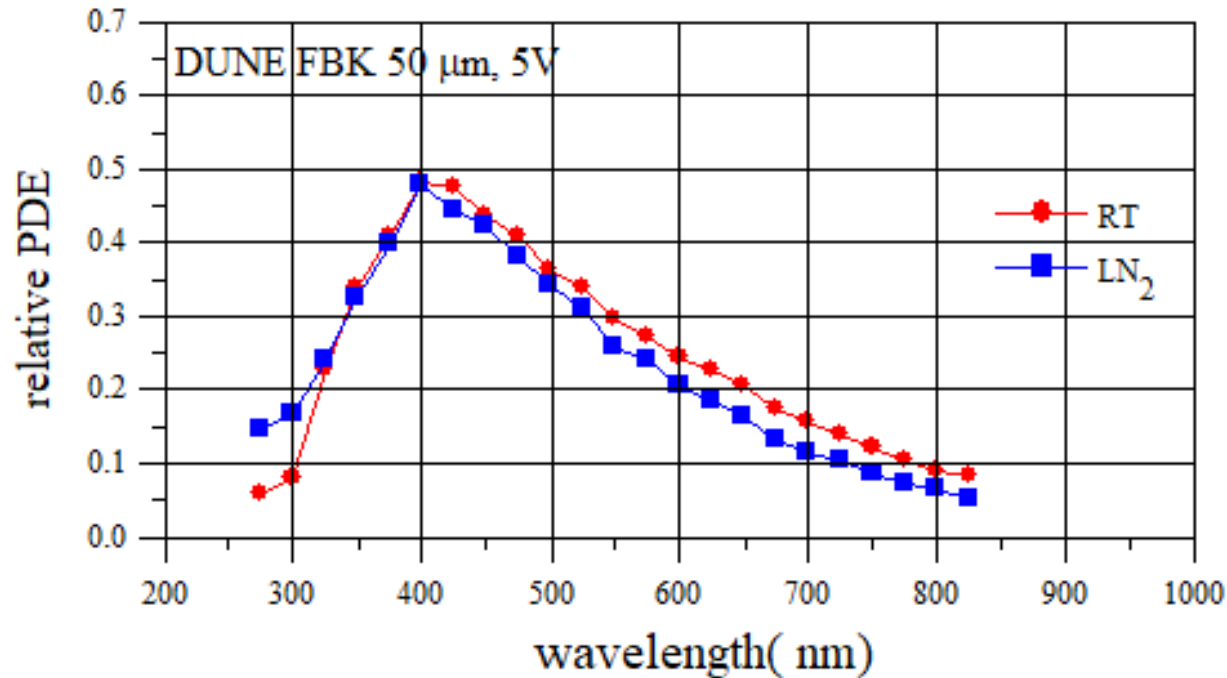
Spectral PDE response generally agrees with HPK (peak at ~460 nm) – also has a slight blue shift behavior in LN₂

DUNE FBK: PDE spectral response – use white light source and calibrate against NIST photodiode

$$PDE_{\lambda} = [spectral\ reponse]_{\lambda} \times \frac{[PDE_{pulse}]_{405nm}}{[spectral\ reponse]_{405nm}}$$

noted: CT & AP – photoelectron effect, wavelength independent

PDE (QE) = photon effect, depends on wavelength



FPK data RT

N/C

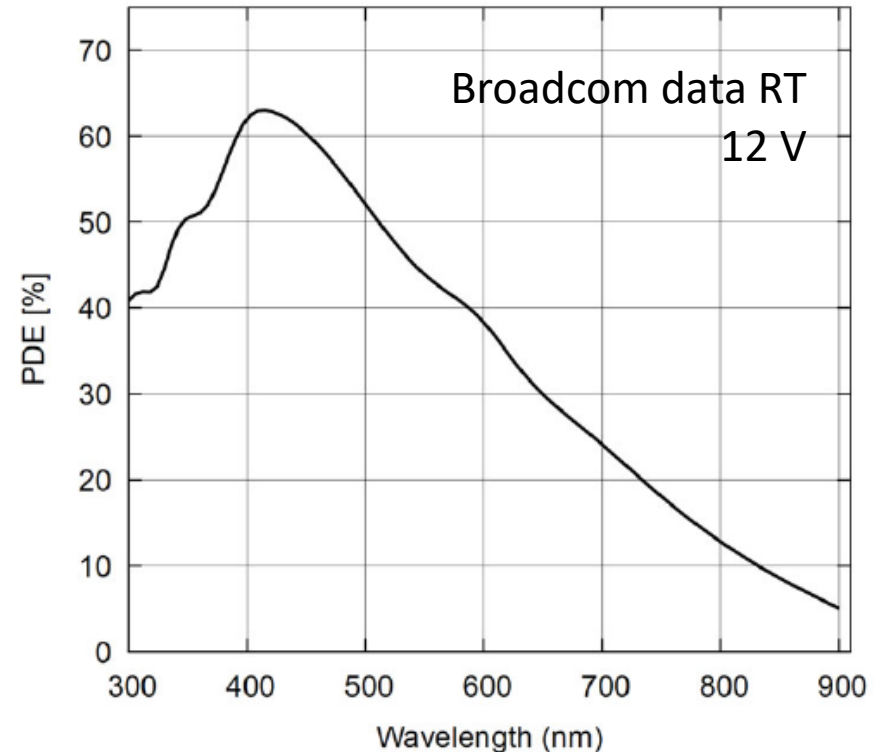
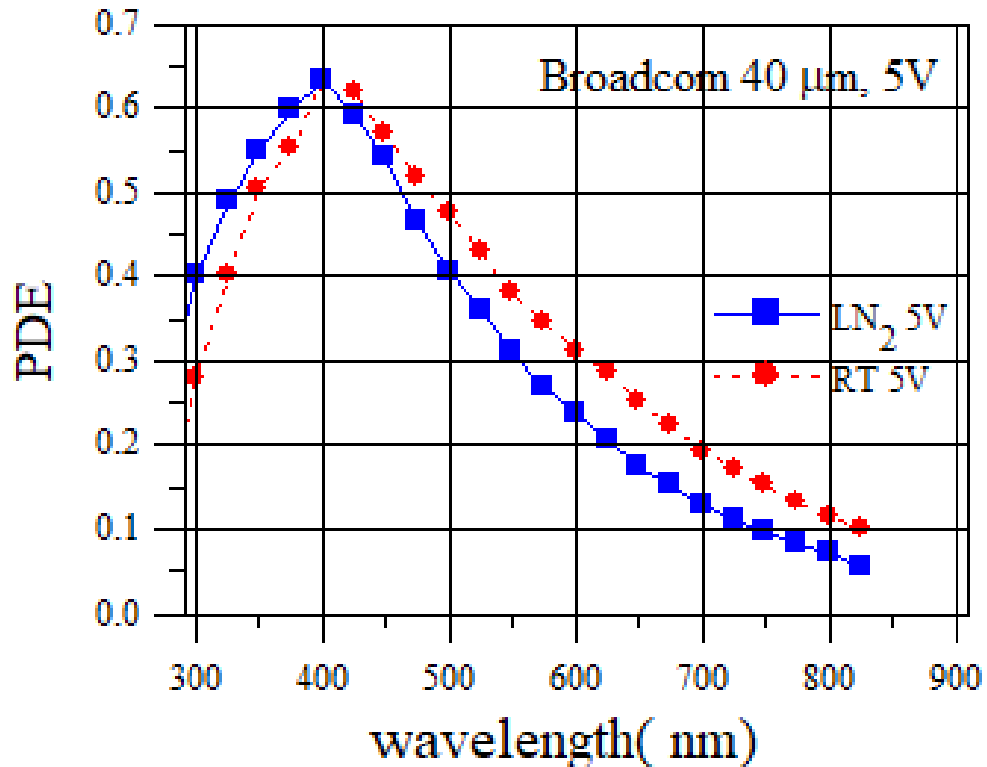
Can't compare to FBK data (peak at ~400 nm) – may have a very slight blue shift behavior in LN₂

Broadcom: PDE spectral response – use white light source and calibrate against NIST photodiode

$$PDE_{\lambda} = [spectral\ reponse]_{\lambda} \times \frac{[PDE_{pulse}]_{405nm}}{[spectral\ reponse]_{405nm}}$$

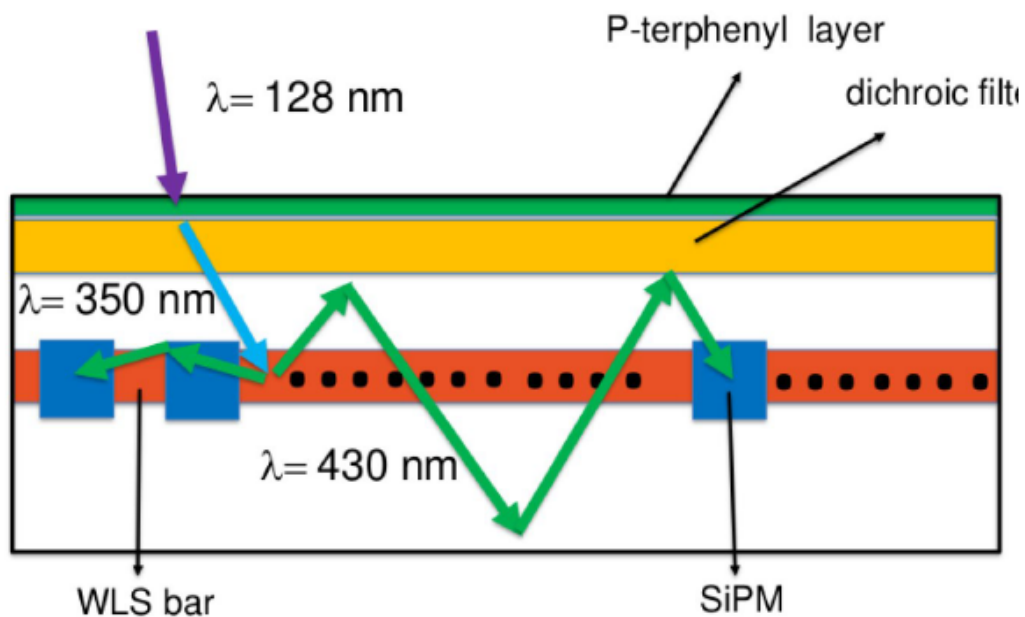
noted: CT & AP – photoelectron effect, wavelength independent

PDE (QE) = photon effect, depends on wavelength



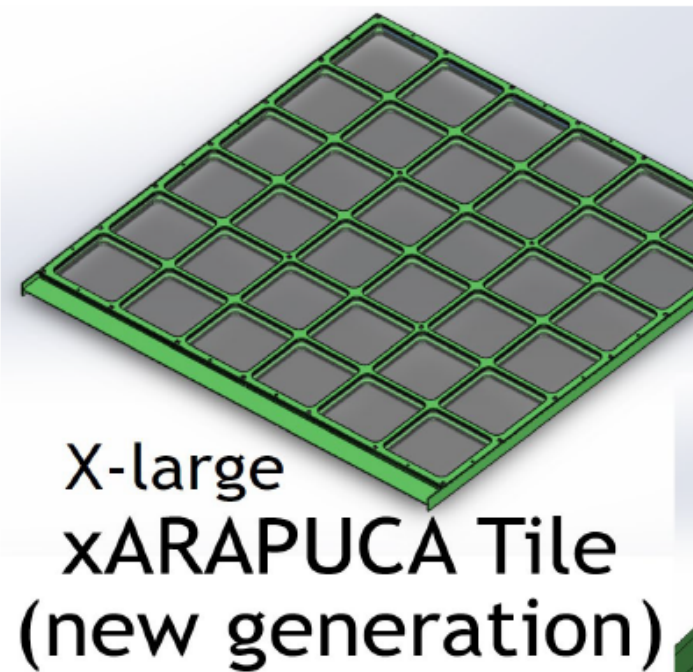
SiPM array readout concept

DUNE FD-2: ARAPUCA (Argon R&D Advanced Program at UniCamp).



Credits: F. Terranova

- 160 SiPMs (40 per side)
 - Glued to WLS Bar for improved optical contact
- SiPMs mounted on Kapton flexi-PCB

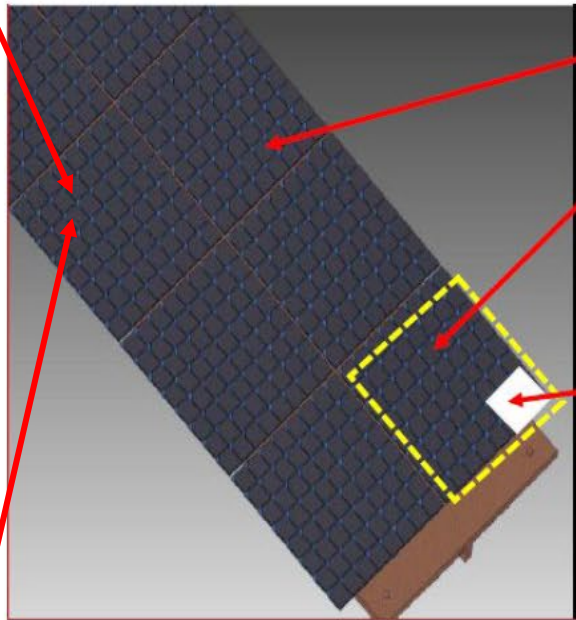
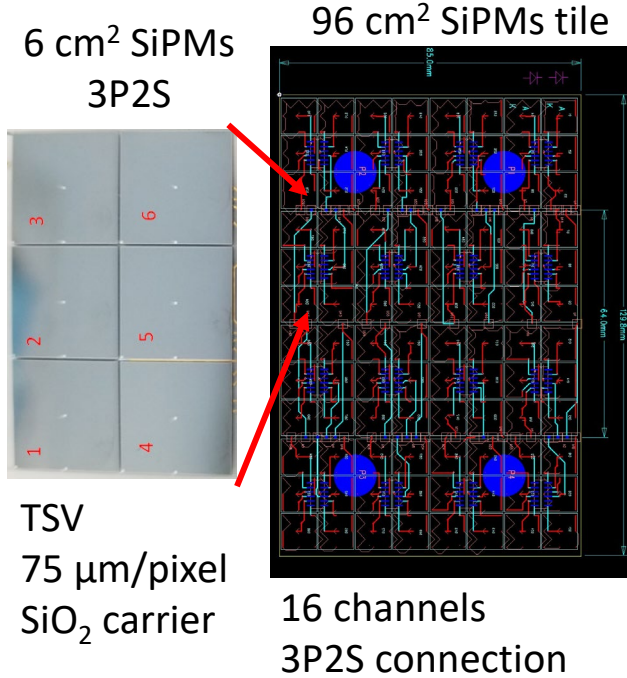


Readout a challenge for DUNE and SBND!

- Optical area
 - 600 mm x 600 mm = 3600 cm²
- SiPM area
 - 160 x 0.36 cm² ≈ 60 cm²
 - ≈ 1.7 % of opt. area
 - SiPM array capacitance ≈ 200 nF for $V_{bd} \sim 45 \text{ V}$;
 - ≈ 260 nF for $V_{bd} \sim 37 \text{ V}$

M.C. Queiroga Bazetto, V.L. Pimentel, A.A. Machado and E. Segreto, in Campinas, Brazil

nEXO SiPM Light Detector Readout

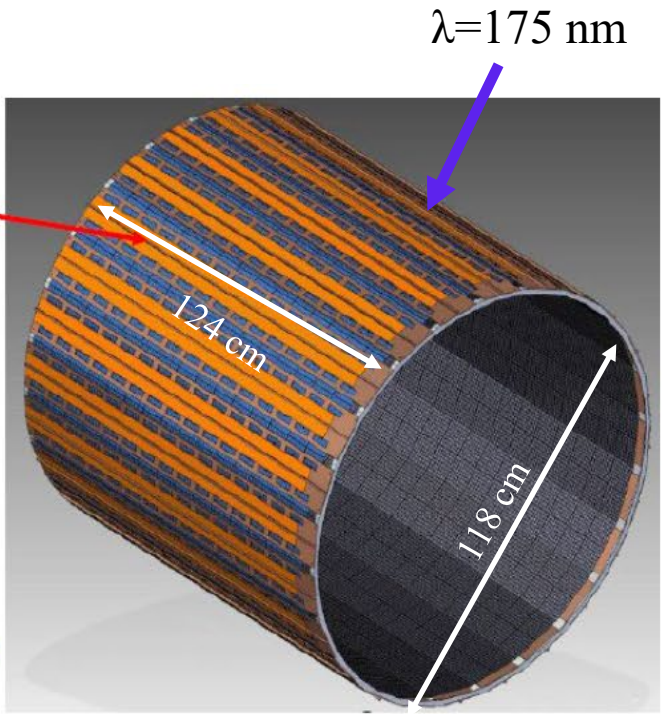


Staves: **24**

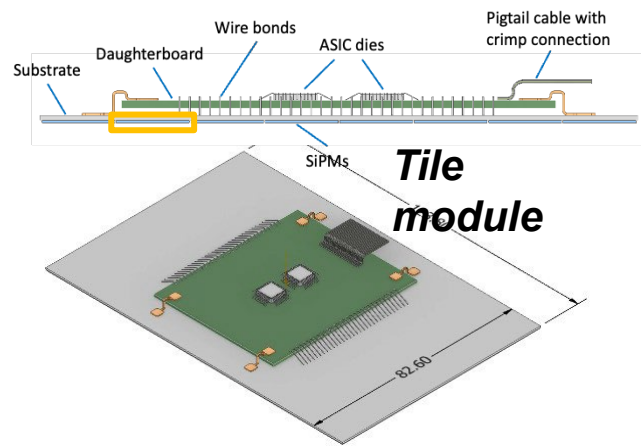
Tiles : **24 x 2 x 10 = 480**

Sub-arrays 6 cm²:
480 x 16 = 7680

SiPM Area: **7680 x 6 cm² = 4.6 m²**



SiPM 'bird cage'

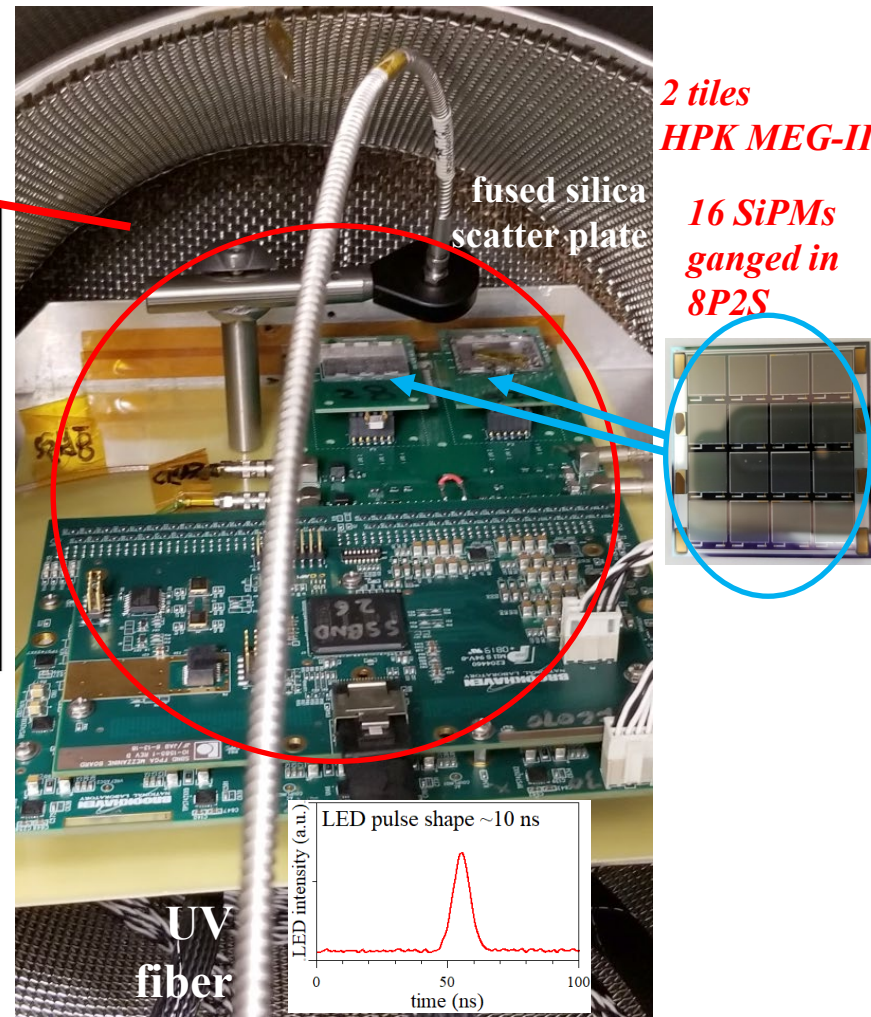
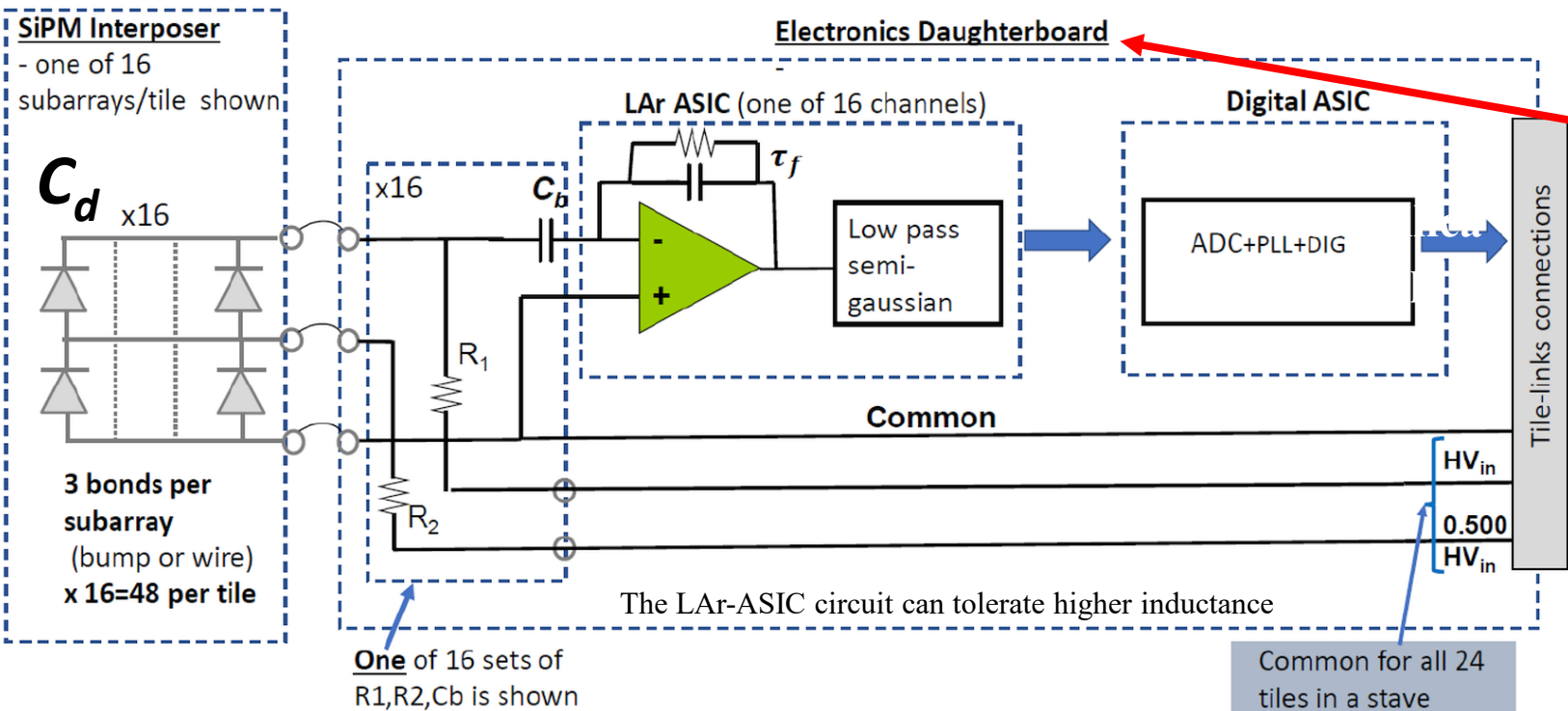


| Technology | | HPK | FBK |
|---|-----|------------|-------------|
| $V_{operating}$ (RT) | [V] | 50 | 30 |
| $C/area$ [nF/cm ²] | | 3.5 | 8.5 |
| C (6 cm ²) / channel [nF] | | 21 | 51 |
| C (8P2S) [nF] | | 5 | 12.5 |
| V (2S) | [V] | 100 | 60 |

Very large subarray capacitance/channel

SNR>10 for single photo electrons & radio-pure components are essential for nEXO.

Demonstration of readout concept: weak coupling to amplifier, $C_b \ll C_d$



LArASIC P2:

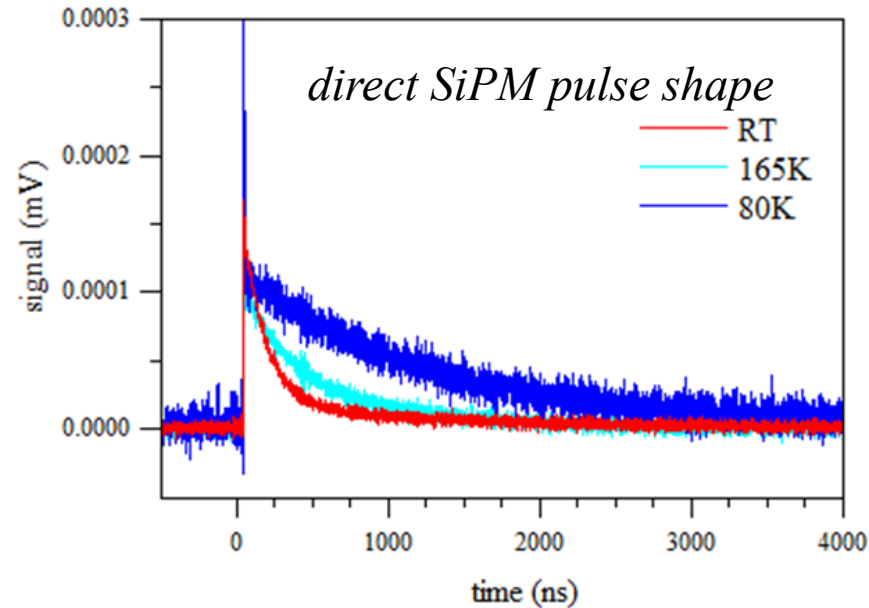
16 **independent** ASIC input channels
 peaking time: **1 μ s** (programmable 0.5, 1, 2, 3 μ s)
 ASIC gain: **4.7 mV/fC** (programmable 7.8, 14, 25 mV/fC)
 $C_{cal}=185$ fF
 ADC sampling rate: 2 MS/s (0.5 μ s/time tick)
 10 MHz ref. clock lock

Reference: channel 0
 Minitile 8P2S: channel 1
 Minitile 8P2S: channel 13
only 2 ASIC channels are used.

LArASIC readout by ADC and FPGA shown in the photo
 Data streaming mode, 45sec/data
 Data collection: LabView
 Data analysis: Python

To know the number of detected photons, the charge of the signal must be measured.
two most common approaches:

- Charge integration
- Amplitude measurement

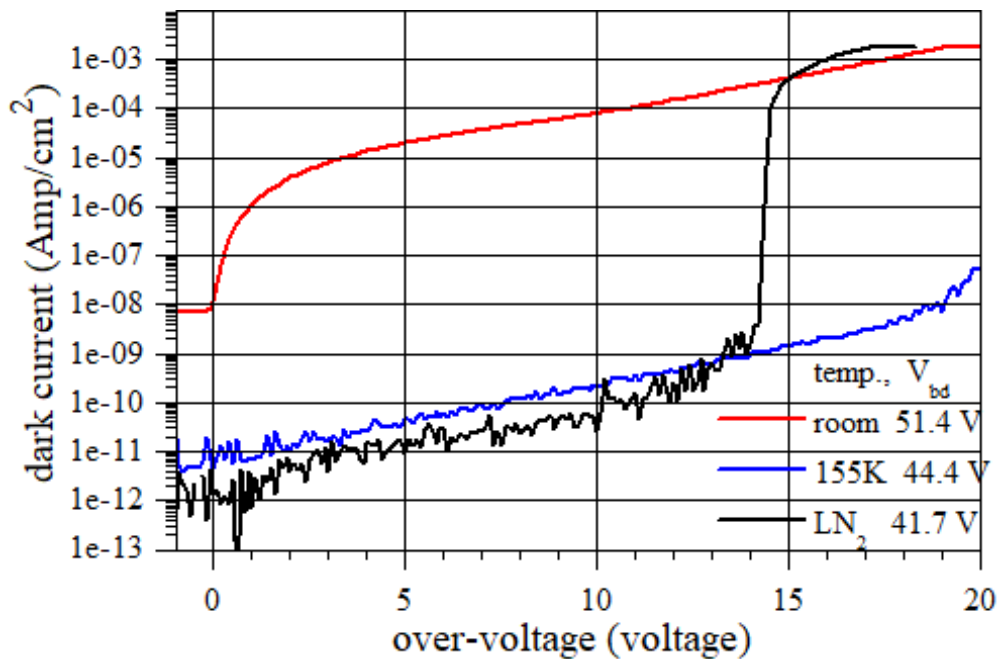


Both methods have their advantages and disadvantages.
or a combination of both

Charge Readout concept: weak coupling to amplifier

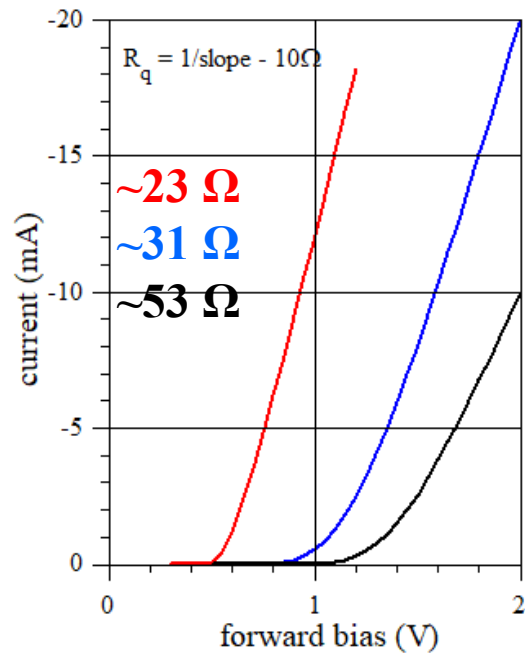
SiPM parameters

IV plots



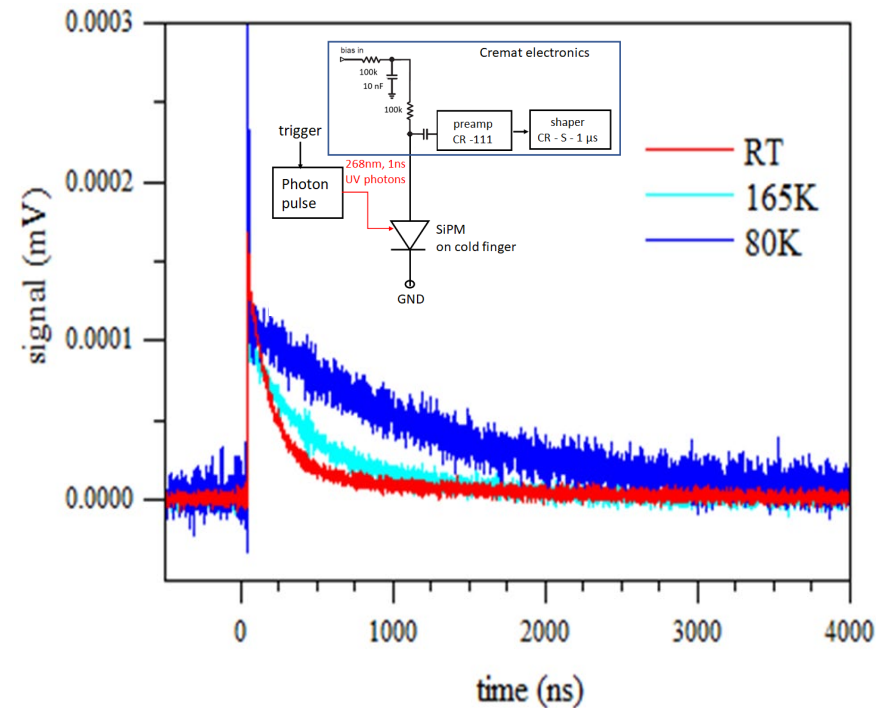
>10 volt operating voltage

quench resistance



R_{quench} increase in cold

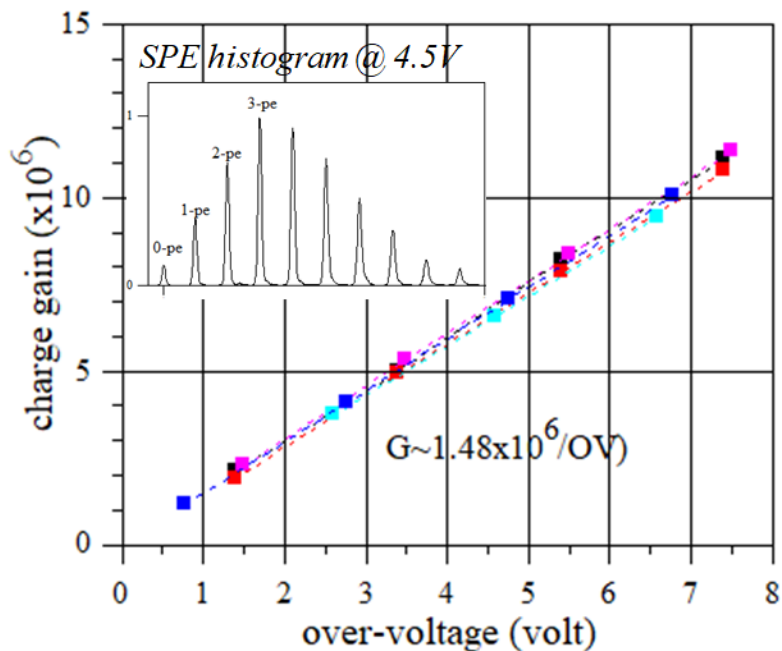
direct SiPM pulse shape



recovery time increase in cold

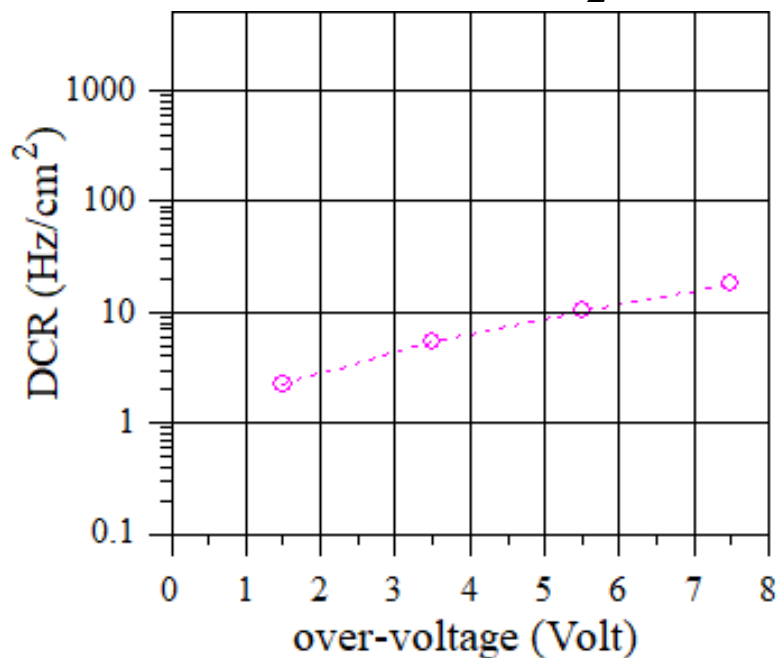
SiPM parameters

charge gain (in LN₂)



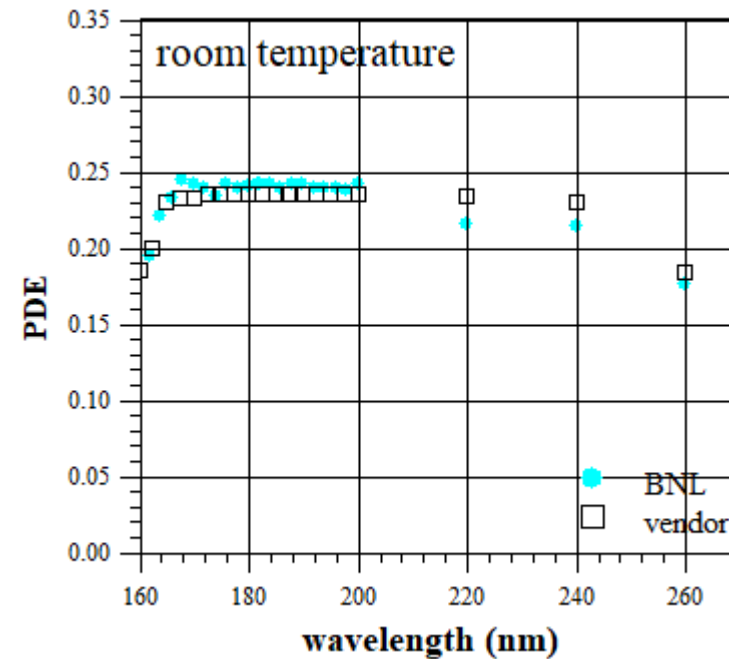
excellent photon number resolving capability

DCR (in LN₂)



extremely low dark rate

PDE (room)

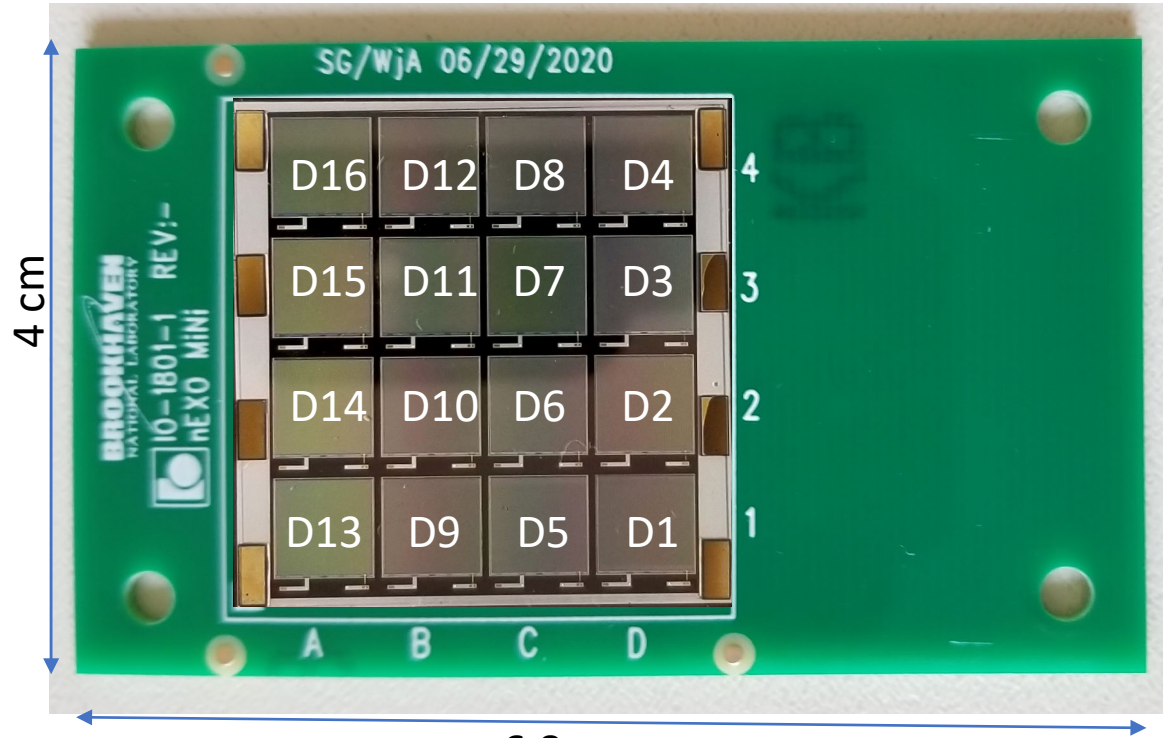


PDE agrees well with vendor

HPK SiPM Minitile arrays

S13775-9121 [4x4x(0.6 cm)²]

HPK minitile board



6.8 cm

active area=5.76 cm²

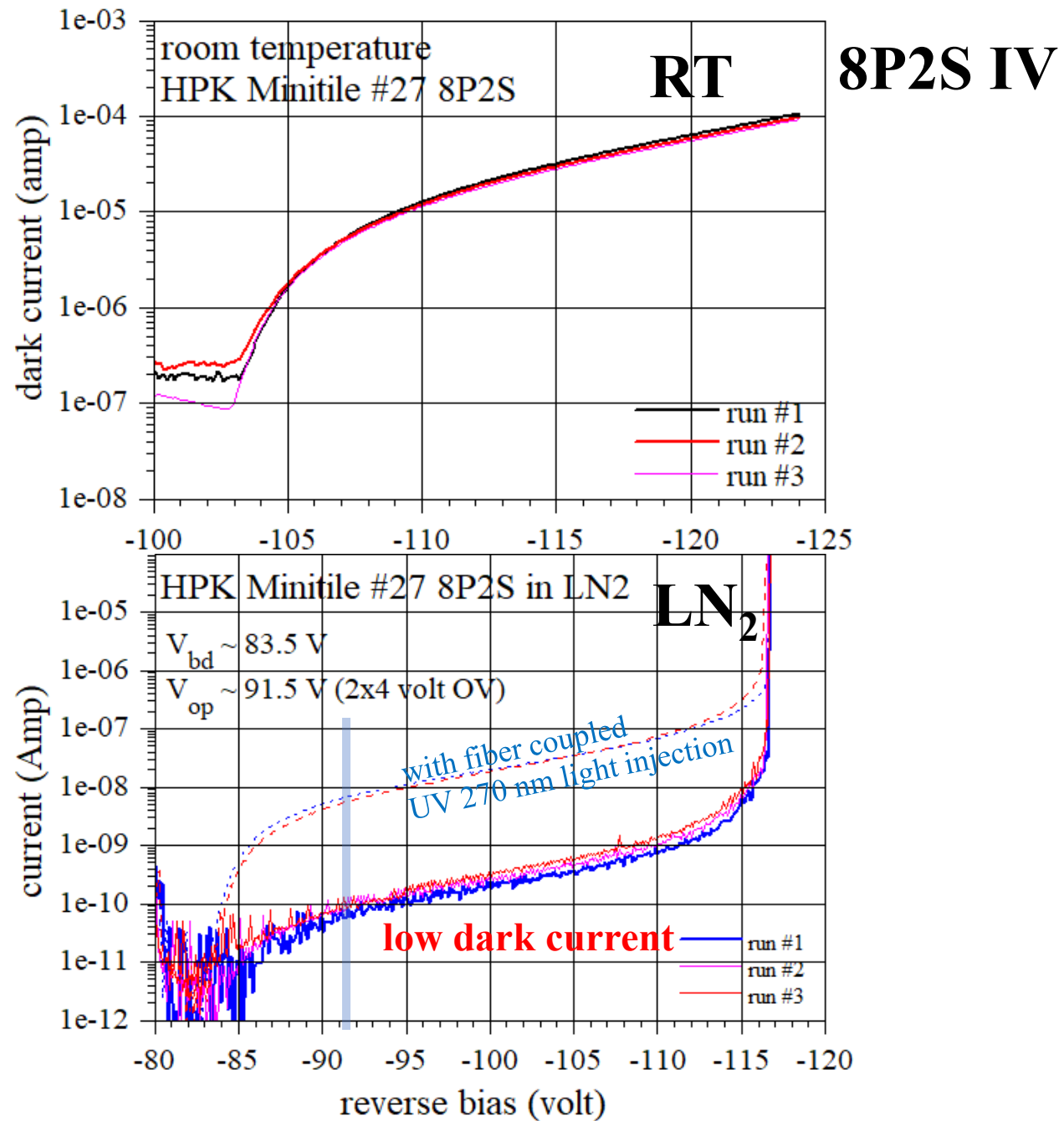
$N_{\text{cell}} = 16 \times 13923 = 222768$ pixels

$C_{\mu\text{cell}}(\text{RT}) = 86$ fF

$C_{\text{Terminal}}(\text{RT}) = 1.2$ nF (3.3 nF/cm²)

$C_{\text{total}}(16\text{P})$ SiPM tile ~ 20 nF

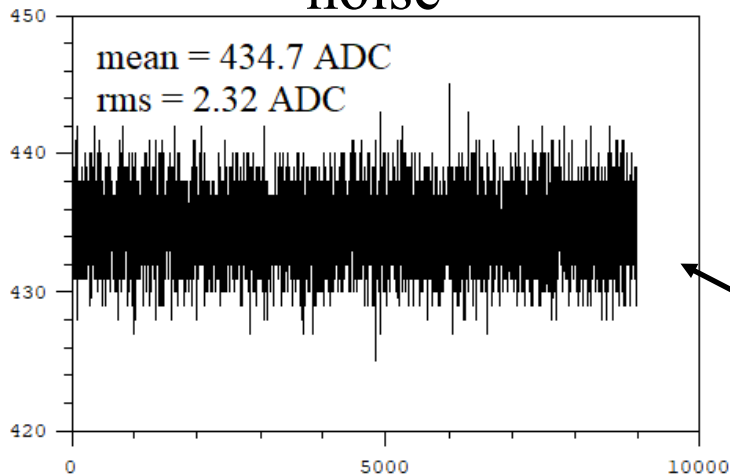
$C_{\text{total}}(8\text{P}2\text{S})$ SiPM tile = 4.8 nF



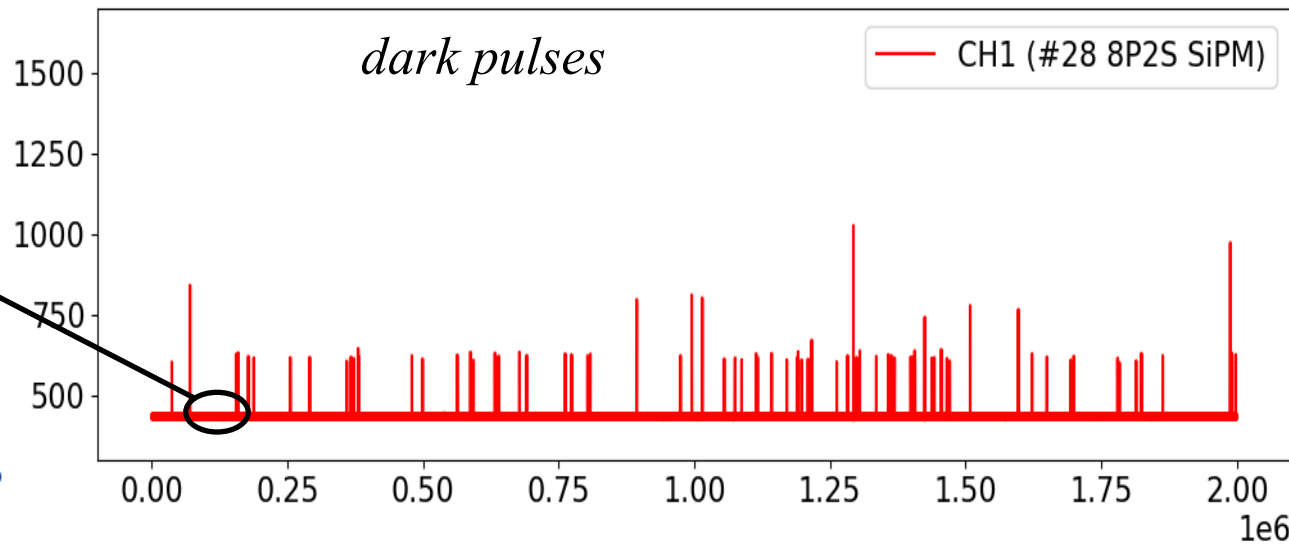
At $\sim 4\text{V OV}$ $I_{\text{dark}}(\text{DCR})$ RT \rightarrow LN₂ drops $\sim 10^{-5}$

in LN₂ @ 4.2 V OV 8P2S 4.8 nF: subset of raw signal trace (1 second)

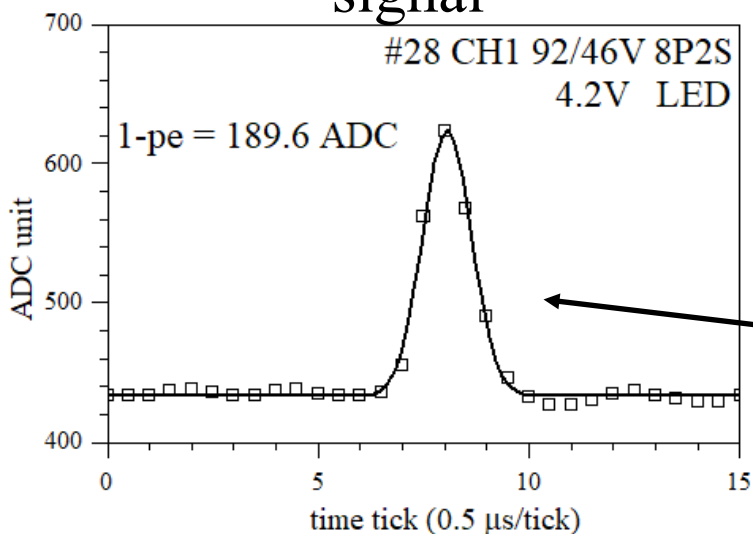
noise



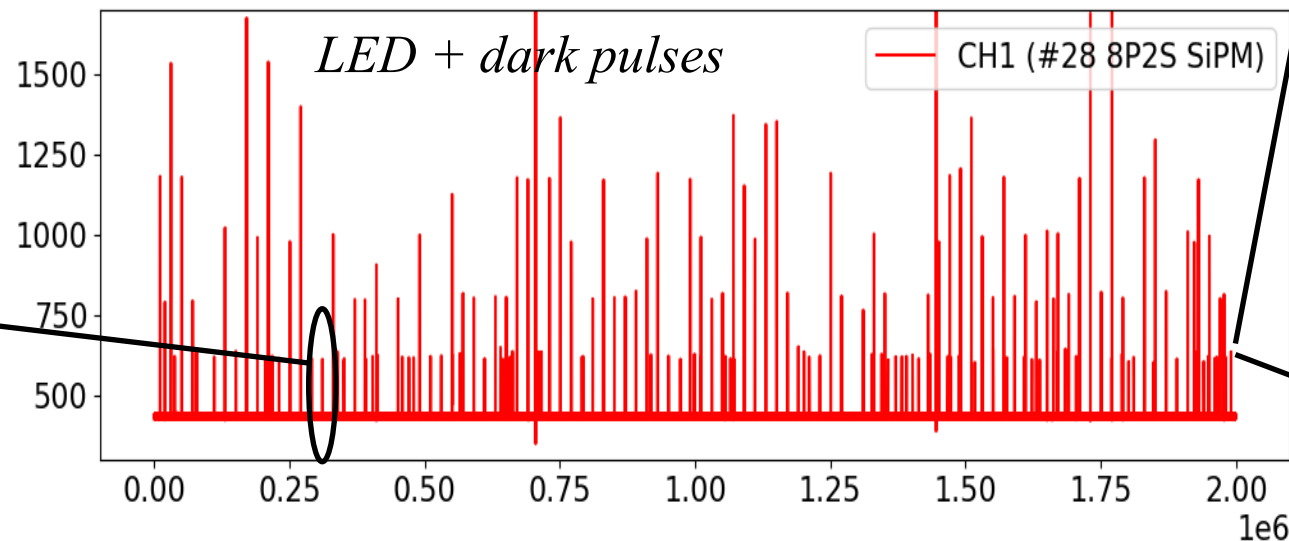
dark pulses



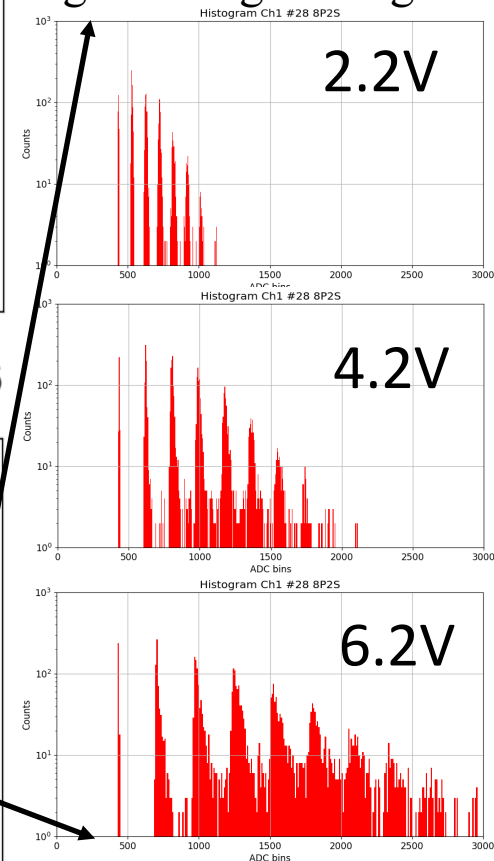
signal



LED + dark pulses



signal charge histogram

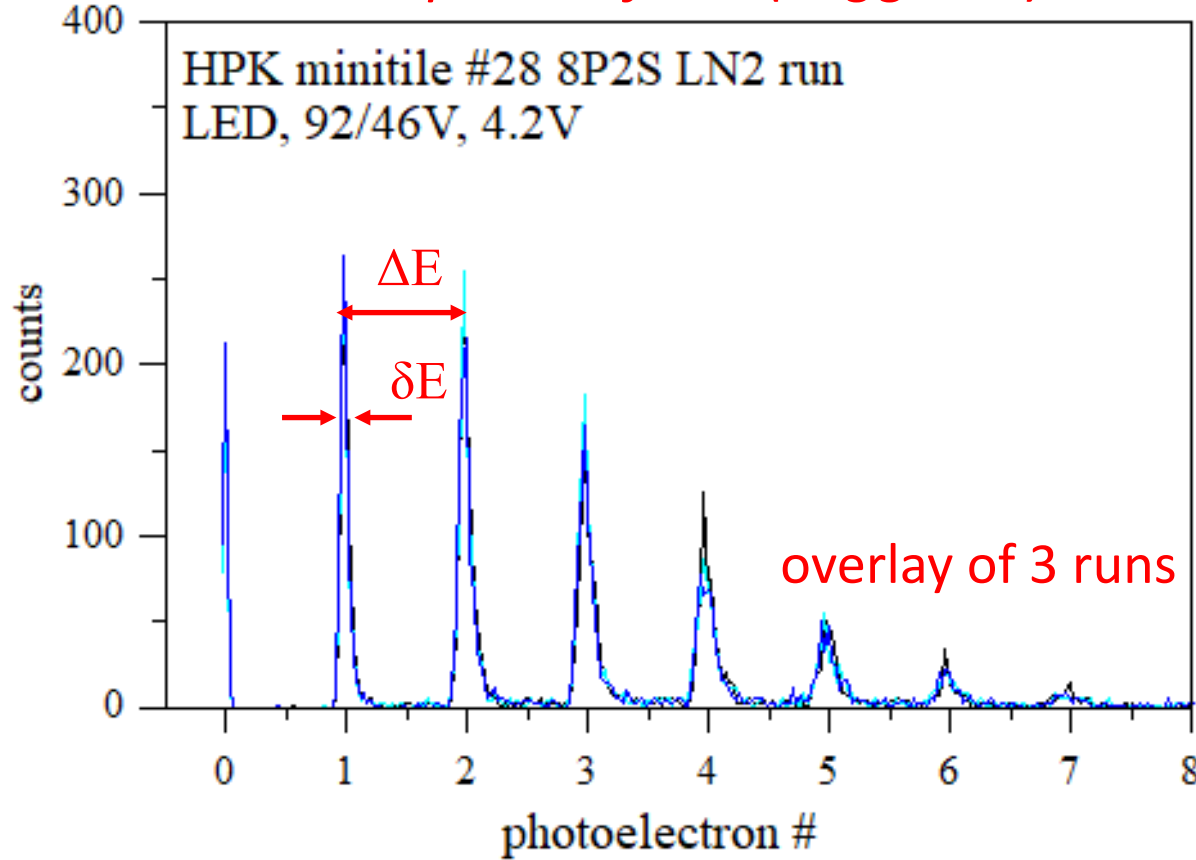


Time tick [0.5 μs/tick] total of 1 second

$$S/N = 189.6/2.32 \approx 82$$

in LN₂: single-photoelectron charge histogram

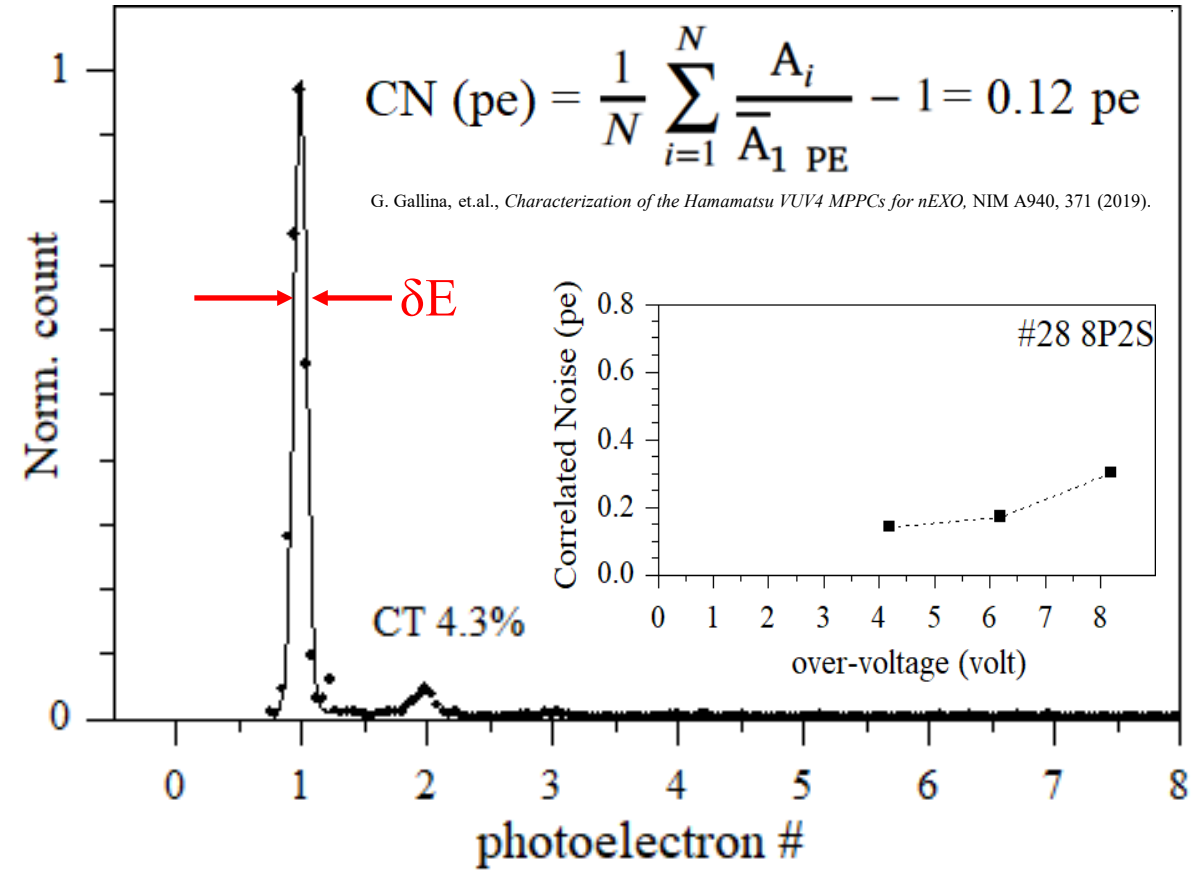
LED photon flash (triggered)



Photon rate: ~80 Hz (trigger rate 100 Hz)

1-pe resolution ($\frac{\delta E}{\Delta E}$): <3.5% rms

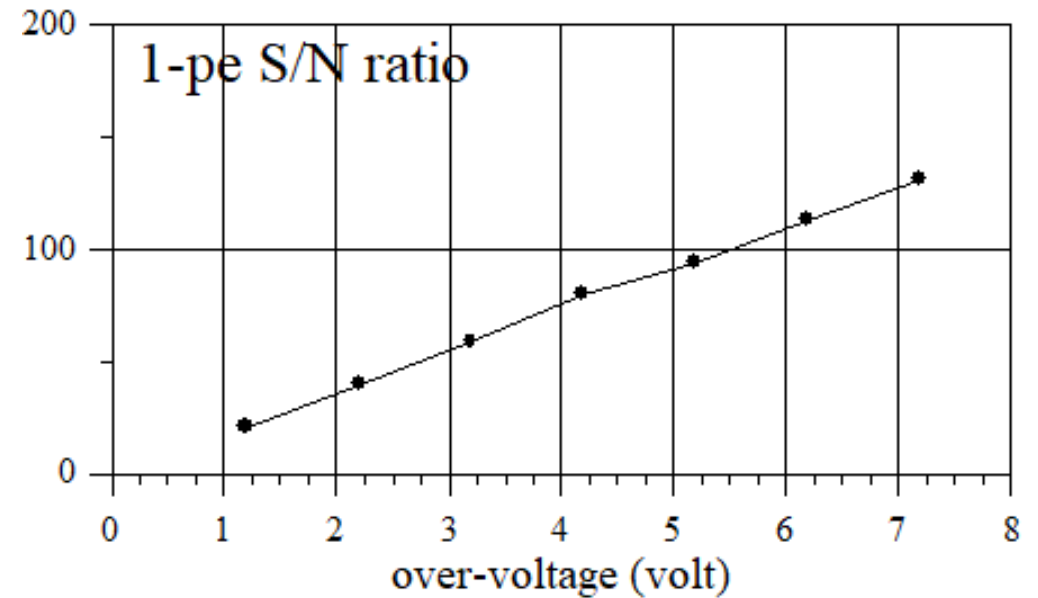
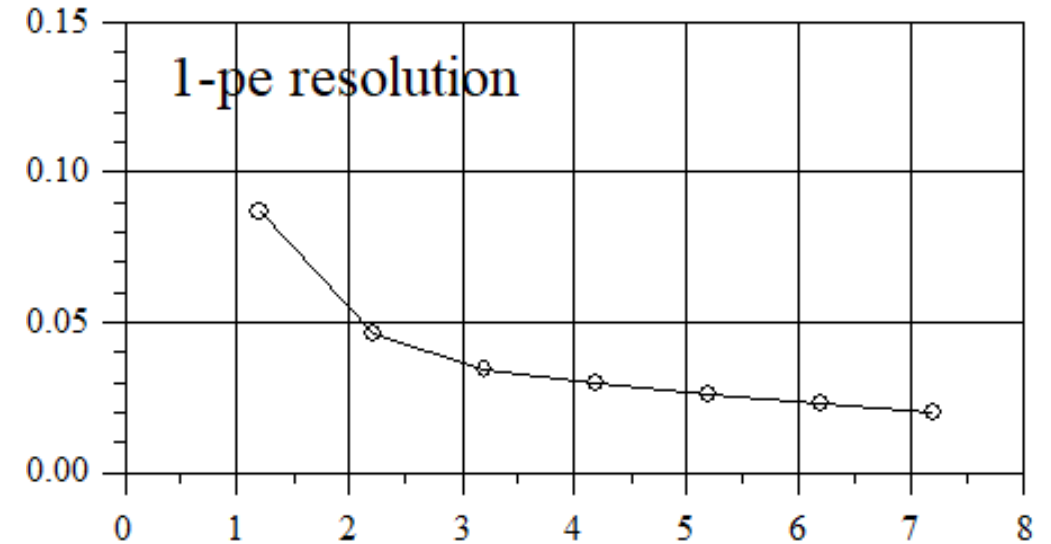
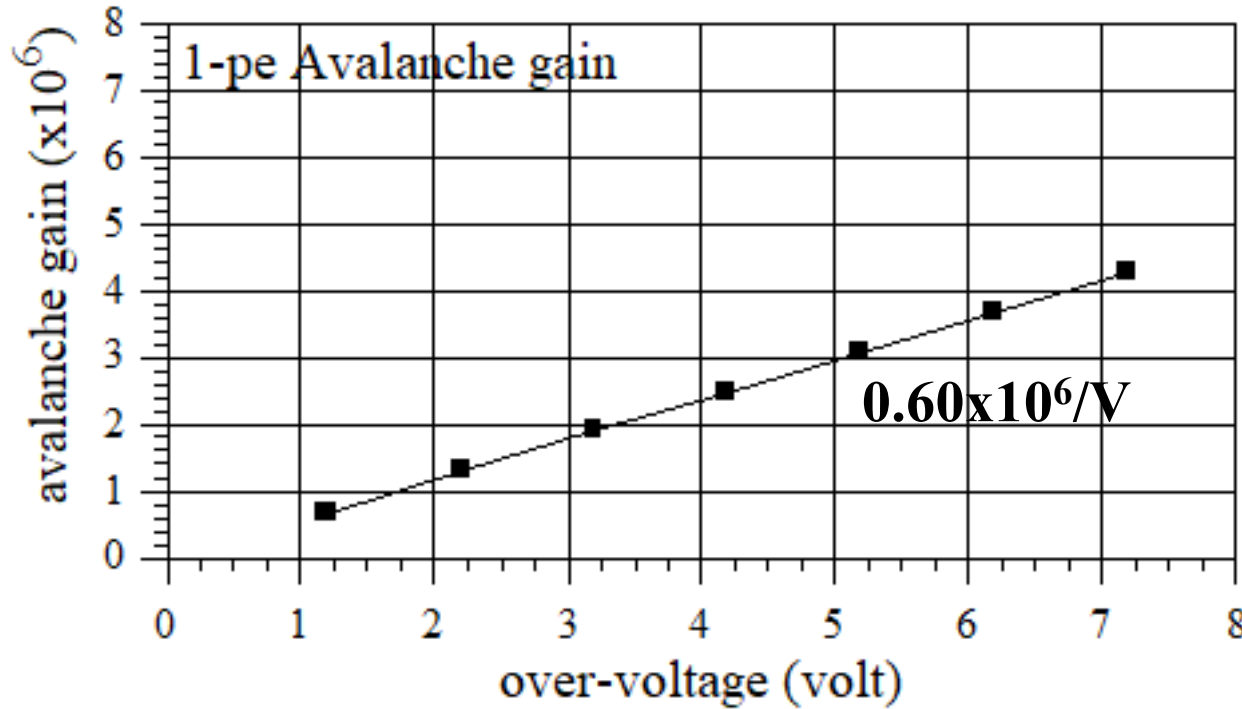
dark pulse



DCR: ~96 Hz (0.17 Hz/mm²)

1-pe resolution: ~5% rms

Avalanche gain, S/N, resolution (8P2S, 4.8 nF), in LN₂



Avalanche gain of both channels are similar

$$\text{Avalanche gain} = \frac{C_{\mu\text{cell}}}{e} (OV)$$

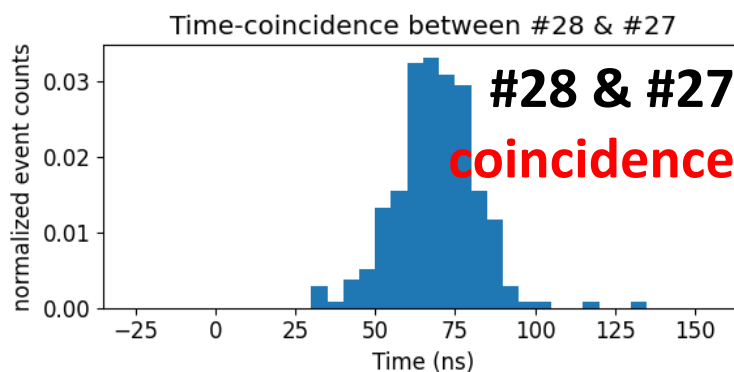
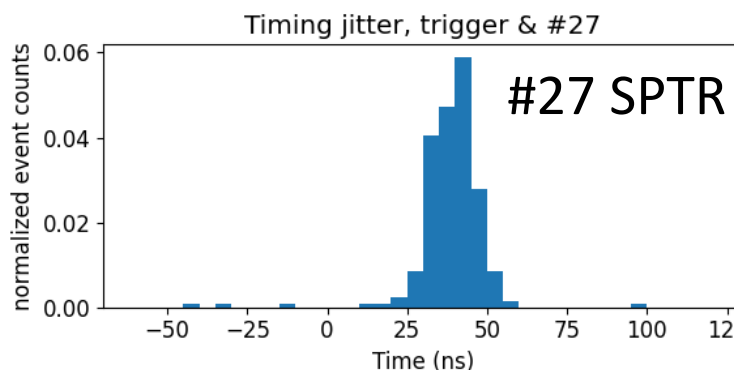
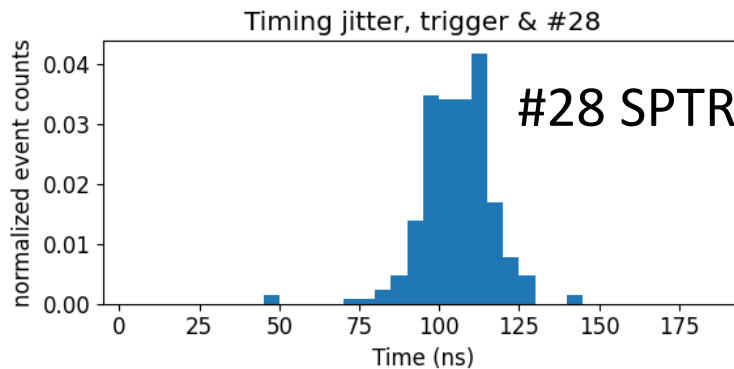
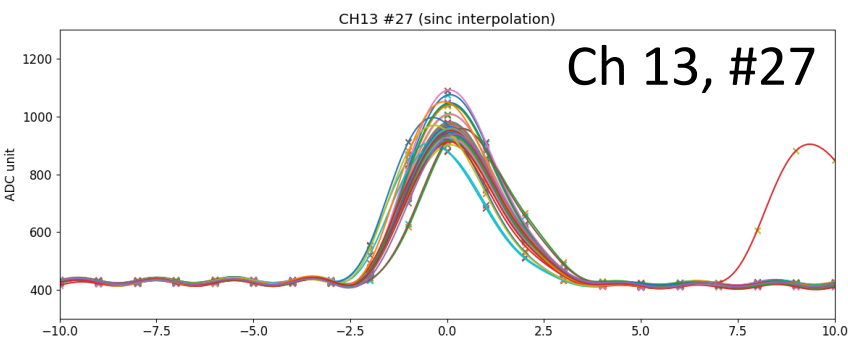
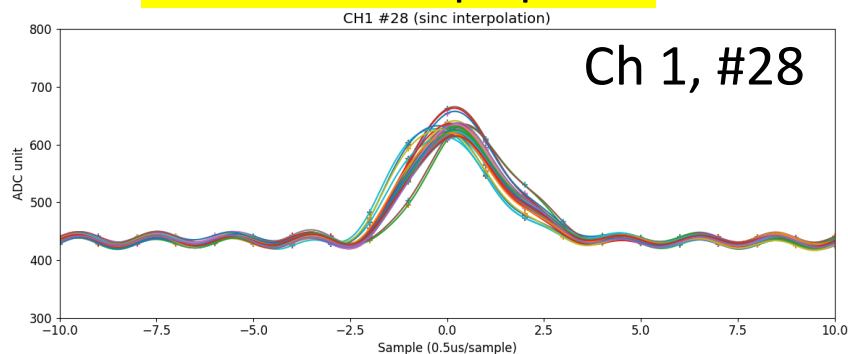
$$C_{\mu\text{cell}} \sim 90 \text{ fF}$$

$$C_{\mu\text{cell}} = \epsilon_0 \epsilon_{\text{Si}} \frac{A}{d}, \text{ d=depletion thickness}$$

Single-Photoelectron Timing and **Coincidence** Resolution

1-pe time jitter histogram, 45 sec data

Select ONLY 1-pe pulses



Photon flash 100 Hz
ADC sampling rate 2 MHz

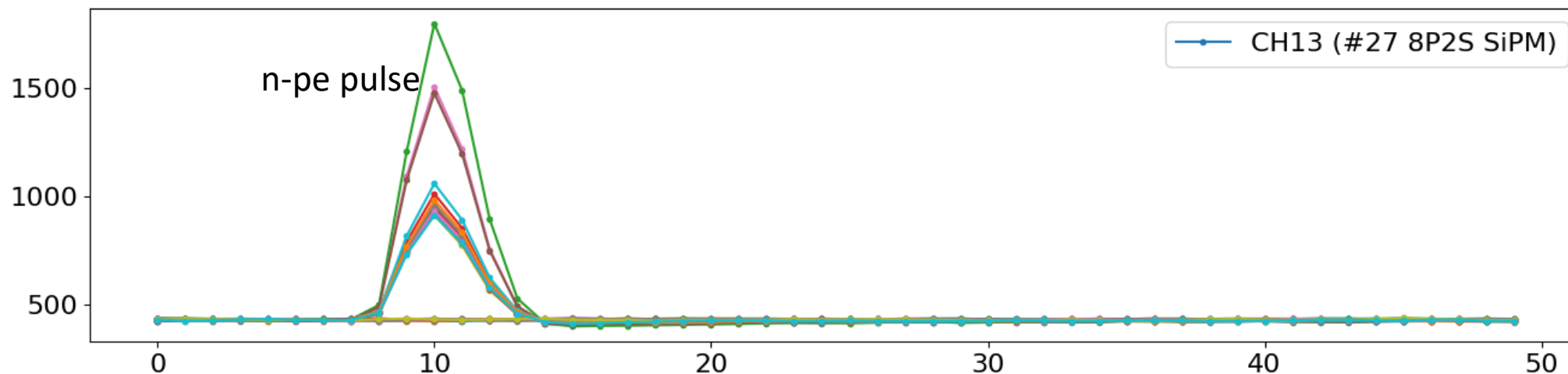
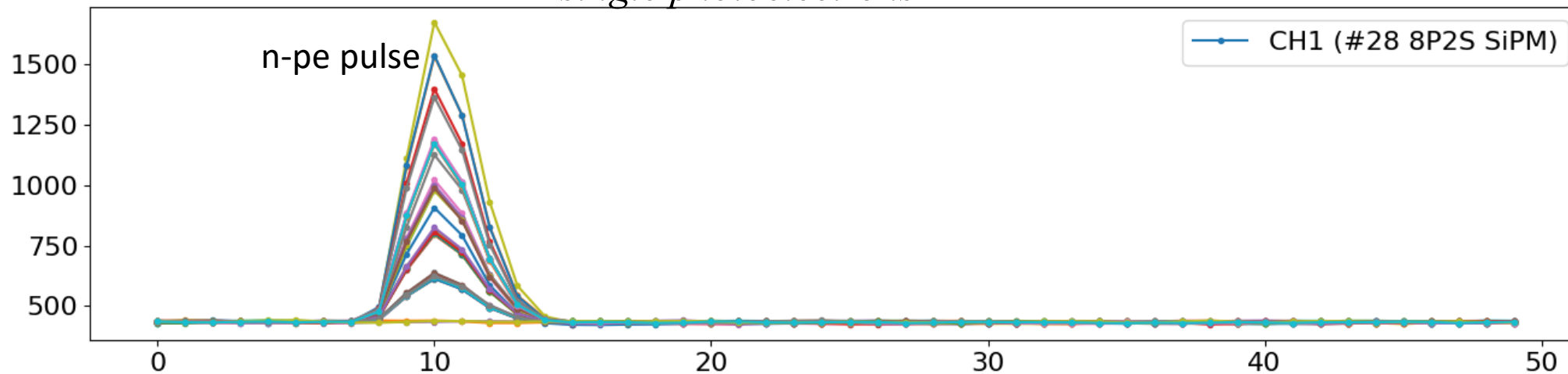
| LN ₂ 4V | Average rate (Hz) | SPTR (ns) |
|-----------------------|----------------------|---------------|
| #28 | 96 | 9.94 |
| #27 | 250.6 | 6.57 |
| Coinc. | 67.3 | ~11 ns |

coincidence
window = 0.5 μs

sinc-interpolation + peak finding led to ~10 ns timing resolution

time coincidence detection: minitiles #27 & #28 – 10 MHz lock ON

single photoelectrons

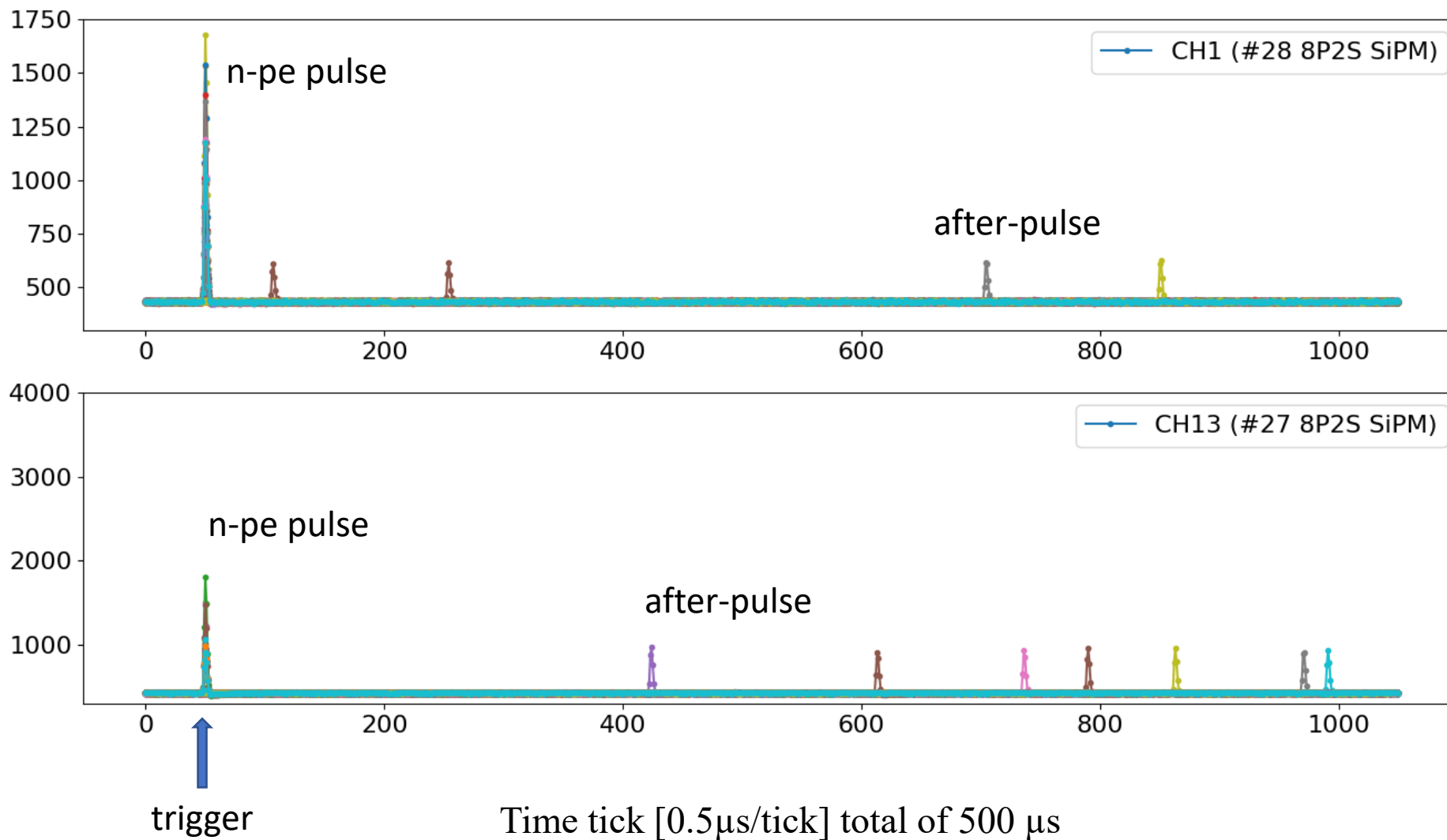


Time tick [$0.5\mu\text{s}/\text{tick}$] total of $500\mu\text{s}$

↑
trigger

Note: #28 and #27 have different charge gain

time coincidence detection: minitiles #27 & #28 – 10 MHz lock ON



after-pulse longer than μs : release of trapped charges after a characteristic time that depends on the type of the trapping centers and its occurrence probability increase in cryogenic temperature.

Mass testing of SiPMs

NIM A610 (2009)

T2K - Japan

Mass production test of Hamamatsu MPPC for T2K neutrino oscillation experiment

M. Yokoyama^{a,*}, T. Nakaya^a, S. Gomi^a, A. Minamino^a, N. Nagai^a, K. Nitta^a, D. Orme^a, M. Otani^a, T. Murakami^b, T. Nakadaira^b, M. Tanaka^b

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For quality assurance of the T2K neutrino detectors

~60,000 SiPMs (HPK) were tested:

gain (G), breakdown voltage (V_{bd}), noise rate (DCR), photo detection efficiency (PDE), and cross-talk (CT) and after-pulse(AP) rate are measured as functions of the bias voltage (V_b) and temp. (T)



NIM A985 (2021)

INFN - Milano

Cryogenic SiPM arrays for the DUNE photon detection system

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For quality assurance of the DUNE photon detection system

100-1000 SiPMs (FBK & HPK) were tested:

cryo-reliability: electric and mechanical stability vs. thermal cycle, I-V curve, Dark Count Rate (DCR) and correlated noise CN(OV). Single photoelectron sensitivity as a function of the total number of sensors connected.



BNL ?



For quality assurance of the FD3-4 photon detection system

test of x # SiPMs (FBK & HPK) are being discussed:

I-V, G, V_{bd} , DCR, CN: CT, AP (OV), relative PDE ...

